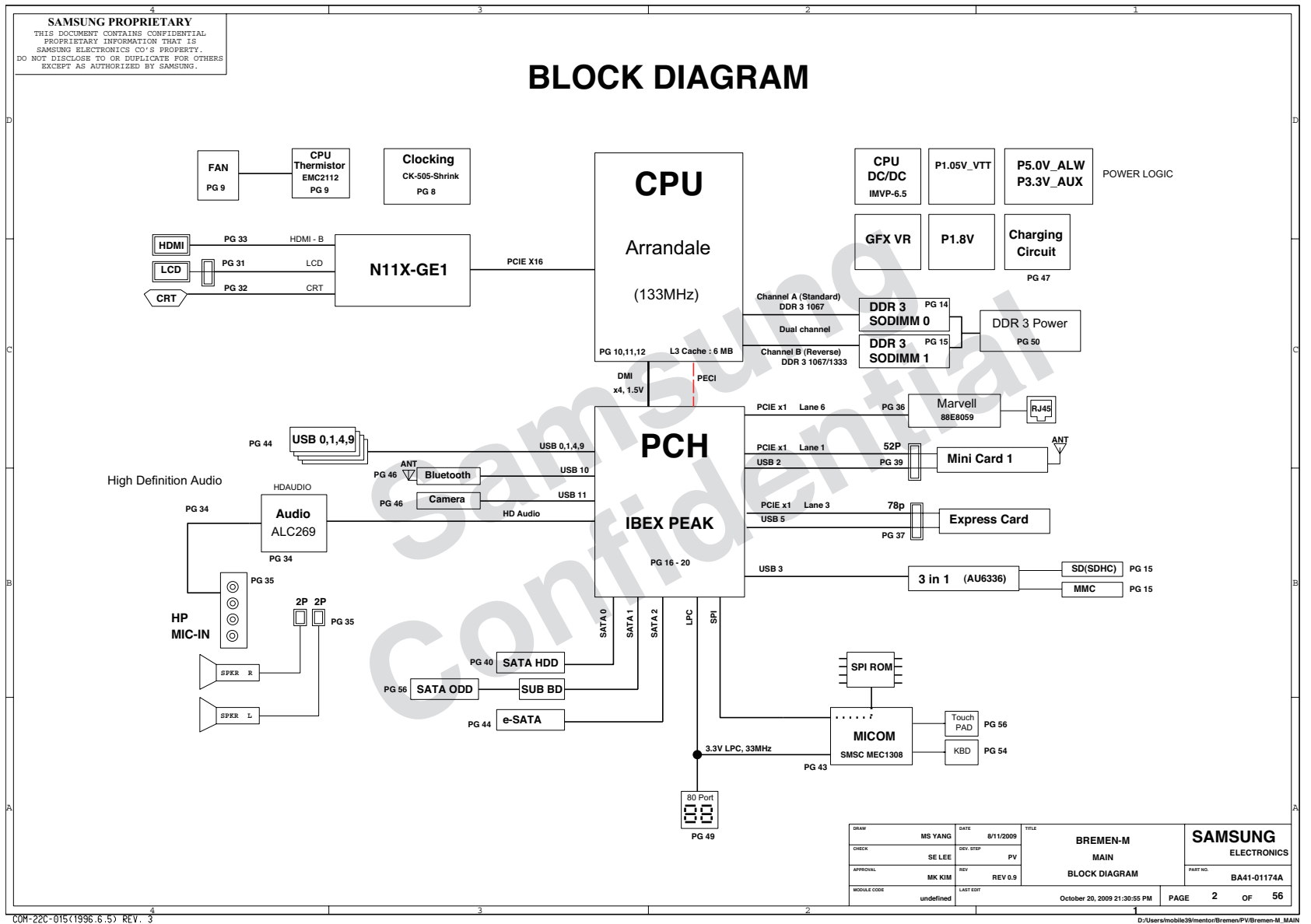


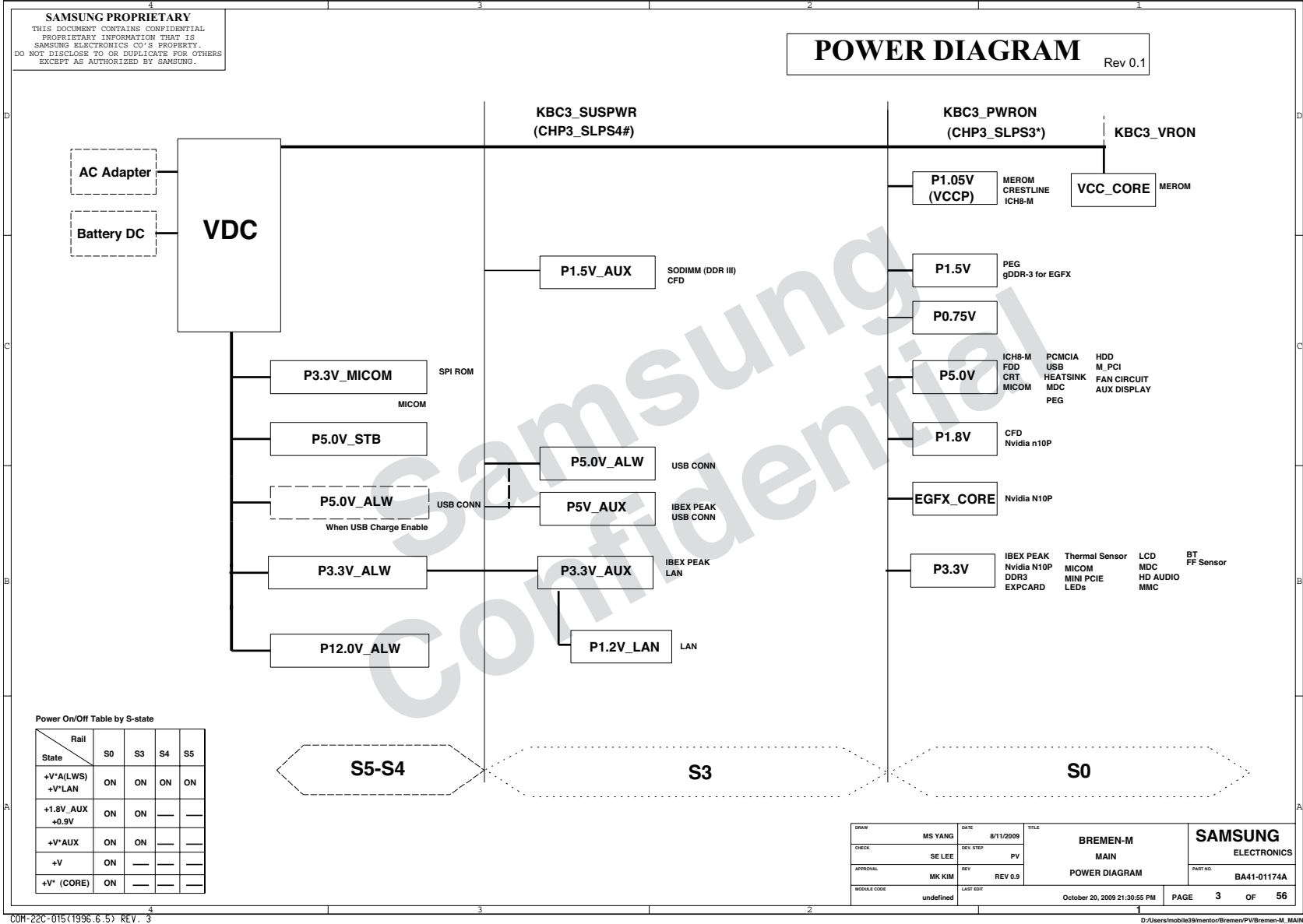
8. Block Diagram and Schematic

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BREMEN-M 15"/17"																																					
CPU : Intel Arrandale																																					
Chip Set : Intel Ixex Peak(PM55)																																					
GFX : N11P/ M-GE1(40nm)																																					
Remarks : Calpella Platform																																					
Model Name : BREMEN-M PBA Name : MAIN PCB Code : BA41-01174A Dev. Step : PV Revision : 0.9 T.R. Date : 2009.10.22																																					
Design	CHECK	APPROVAL																																			
Owner : SEC Mobile R & D Signature : X																																					
Sheet 1. Cover Sheet 2-6. Diagram (Block/Power) & Annotations Sheet 7. Clock Generator -CK505 Shrink Version Sheet 8. Thermal Sensor & FAN Sheet 9-12. Arrandale CPU Sheet 13. DDR3 SODIMM A Sheet 14. DDR3 SODIMM B Sheet 15-19. IBEX PEAK Sheet 20-24. GFx_External_N11X Sheet 25-28. Graphics_Memory_gDDR3 1g bit Sheet 29. Graphic Strap Sheet 30-32. Graphic Interface Sheet 33-34. High Definition Audio (ALC269Q-GR) Sheet 35. LAN_Marvell_88E8059 Sheet 36. Express_Card Sheet 37. MultiCard_AU6336 (3 in 1) Sheet 38. PCIE_Minicard_Slot (Half type only) Sheet 39. SATA_I/F_CONN Sheet 40. MICOM_MEC1308-NU Sheet 41. Micom Glue Logic Sheet 42. LED_Switch Sheet 43. USB Port Sheet 44. Touchpad LED Sheet 45. USB Interface Sheet 46. Charger Sheet 47. PWR_3V_5V Sheet 48. PWR_Calpella Sheet 49. PWR_Memory Sheet 50. PWR_CPU_VRM Sheet 51. PWR_GFX_Ext Sheet 52. PWR_MV_Switched Sheet 53. PWR_MV_DisCharger Sheet 54. 2 USB Port & Power S/W SUB B'D Sheet 55. SATA ODD SUB B'D Battery IF B'D Sheet 56. EMC Capacitor & ICT Port																																					
<table><tr><td>DESIGN</td><td>MS YANG</td><td>DATE</td><td>8/11/2009</td><td>TITLE</td><td>BREMEN-M</td><td>SAMSUNG</td></tr><tr><td>CHECK</td><td>SE LEE</td><td>DEV. STEP</td><td>PV</td><td></td><td>MAIN</td><td>ELECTRONICS</td></tr><tr><td>APPROVAL</td><td>MK KIM</td><td>REV</td><td>REV 0.9</td><td></td><td>COVER</td><td>PART NO.</td></tr><tr><td colspan="4">MODULE CODE</td><td>LAST EDIT</td><td>October 20, 2009 21:30:55 PM</td><td>BA41-01174A</td></tr><tr><td colspan="5"></td><td>PAGE</td><td>1 OF 56</td></tr></table>			DESIGN	MS YANG	DATE	8/11/2009	TITLE	BREMEN-M	SAMSUNG	CHECK	SE LEE	DEV. STEP	PV		MAIN	ELECTRONICS	APPROVAL	MK KIM	REV	REV 0.9		COVER	PART NO.	MODULE CODE				LAST EDIT	October 20, 2009 21:30:55 PM	BA41-01174A						PAGE	1 OF 56
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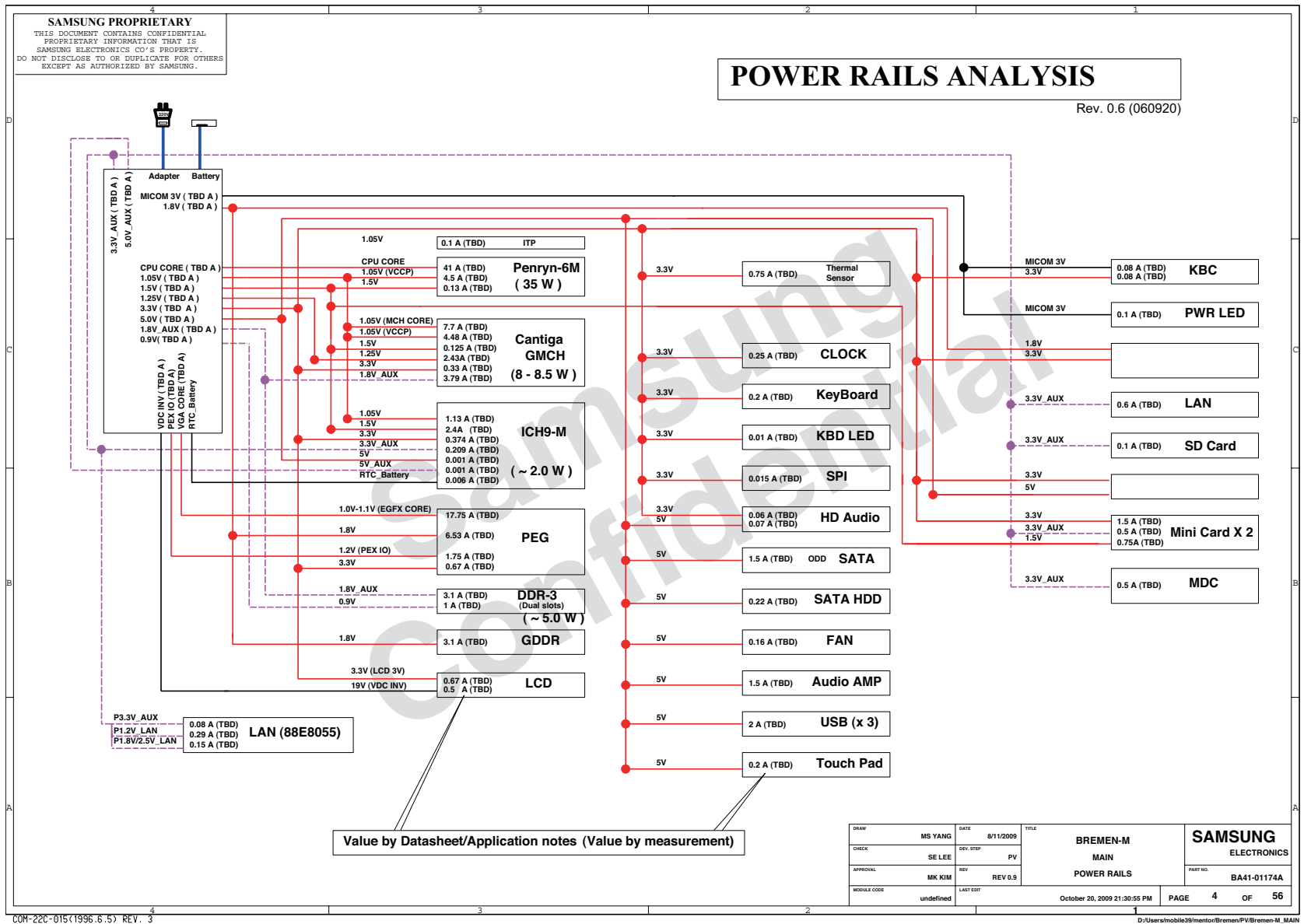
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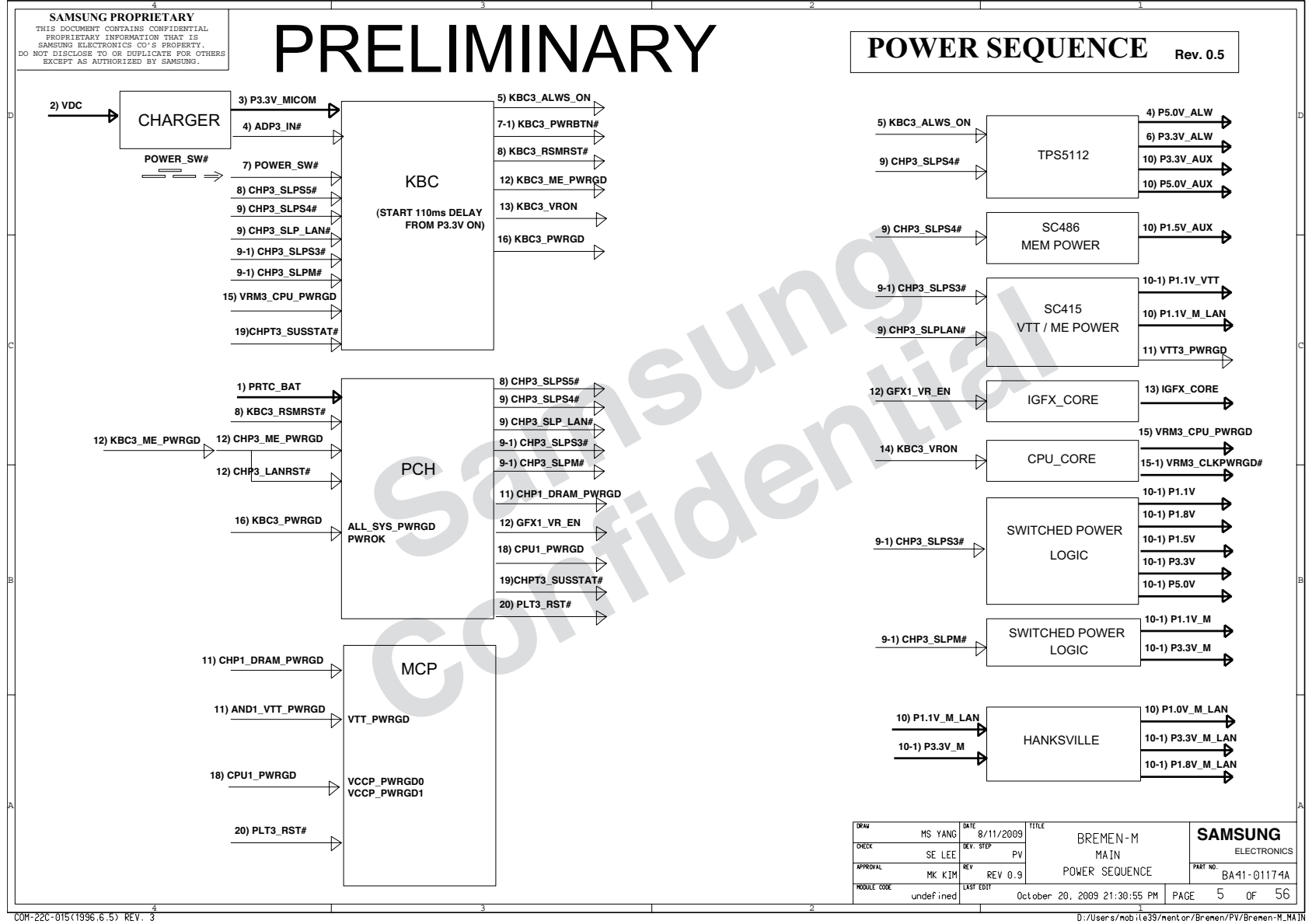
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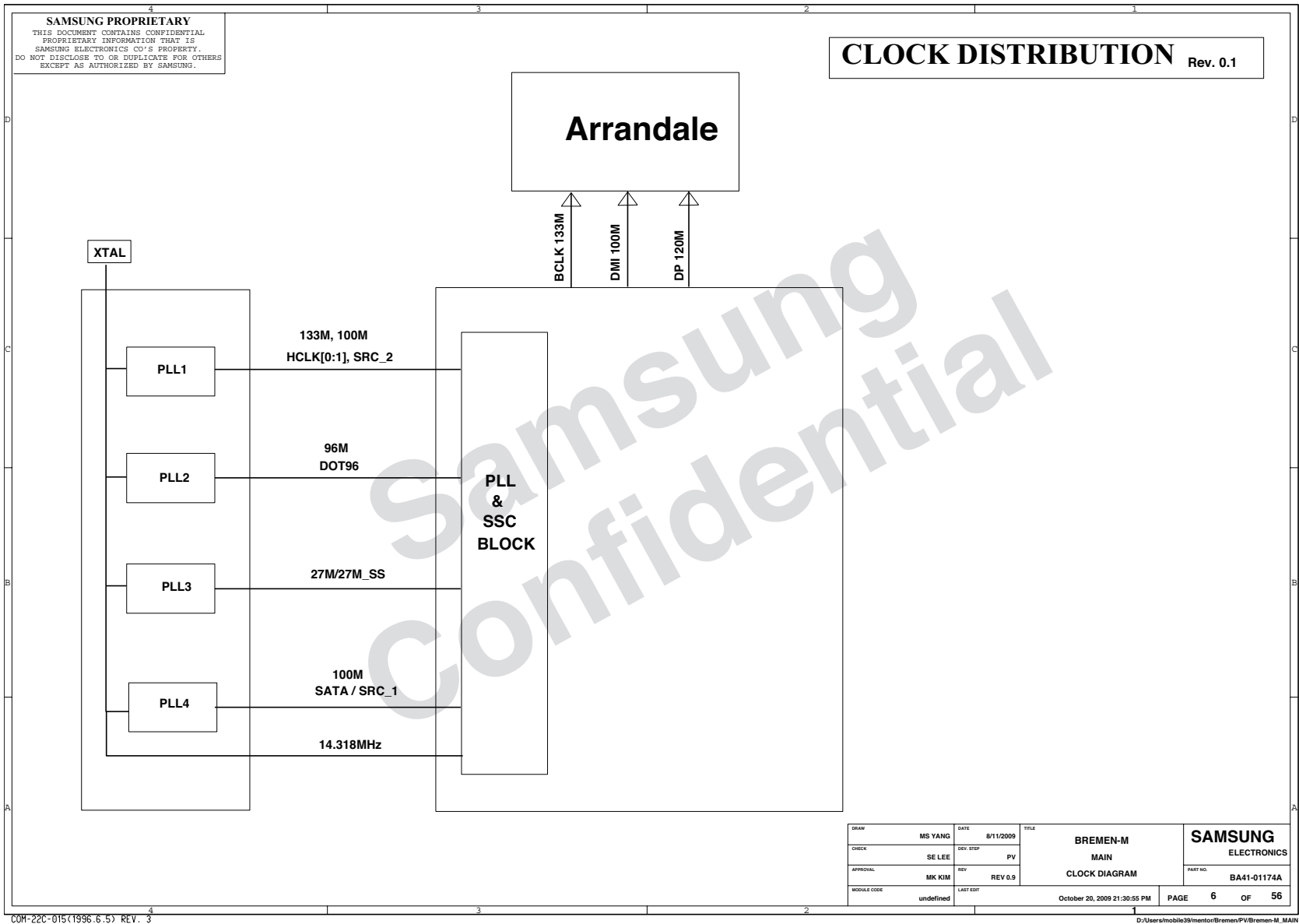
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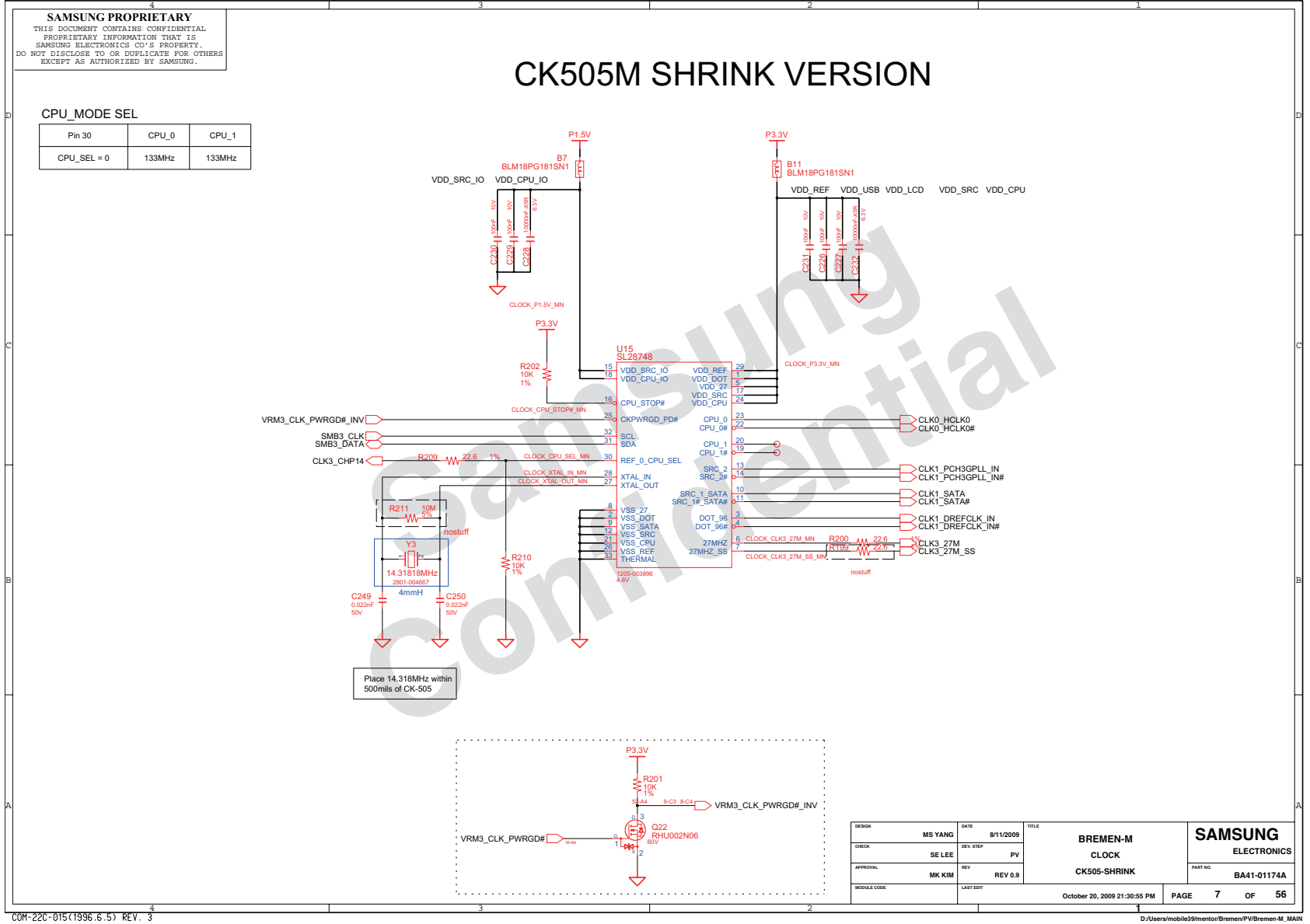
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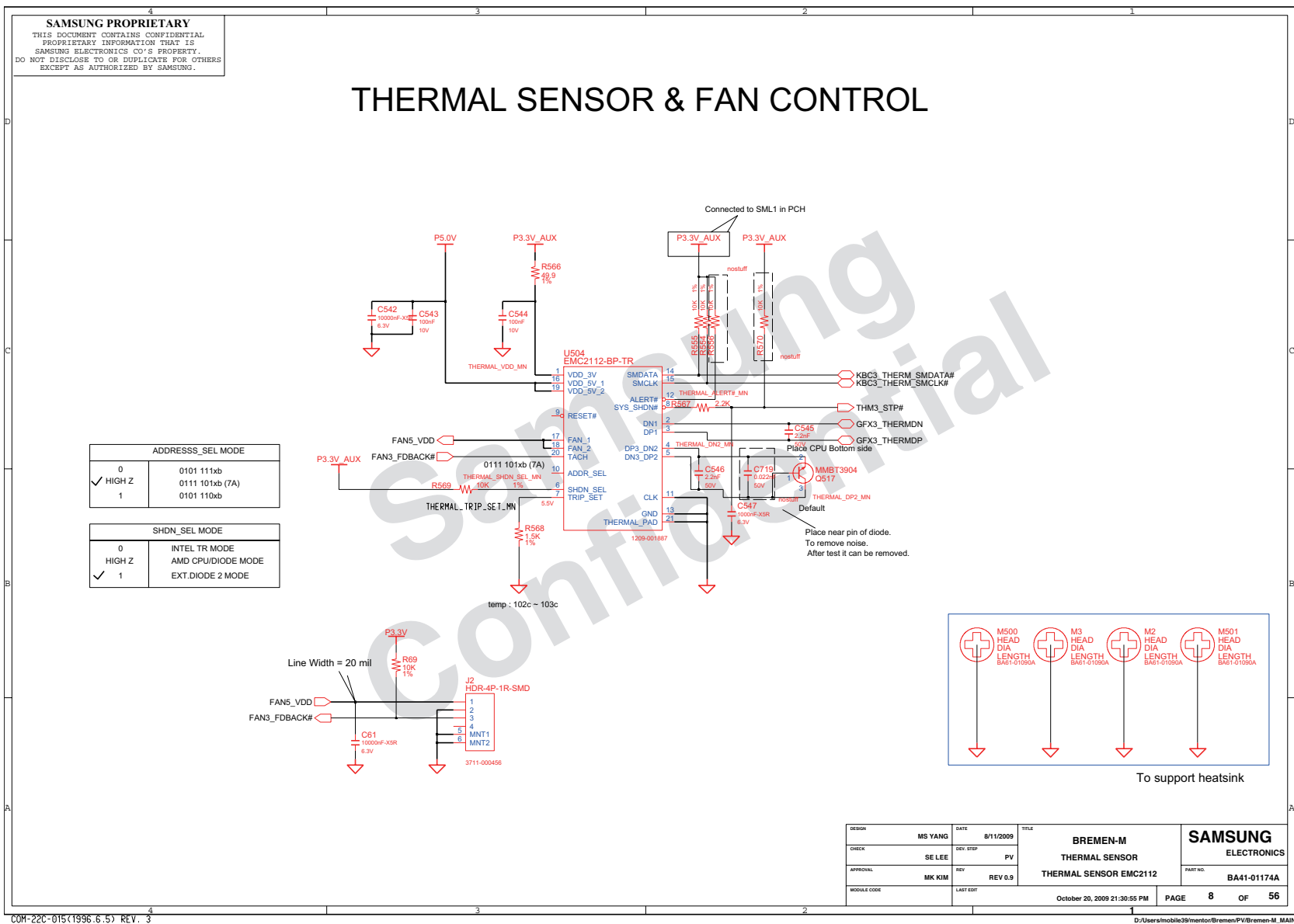
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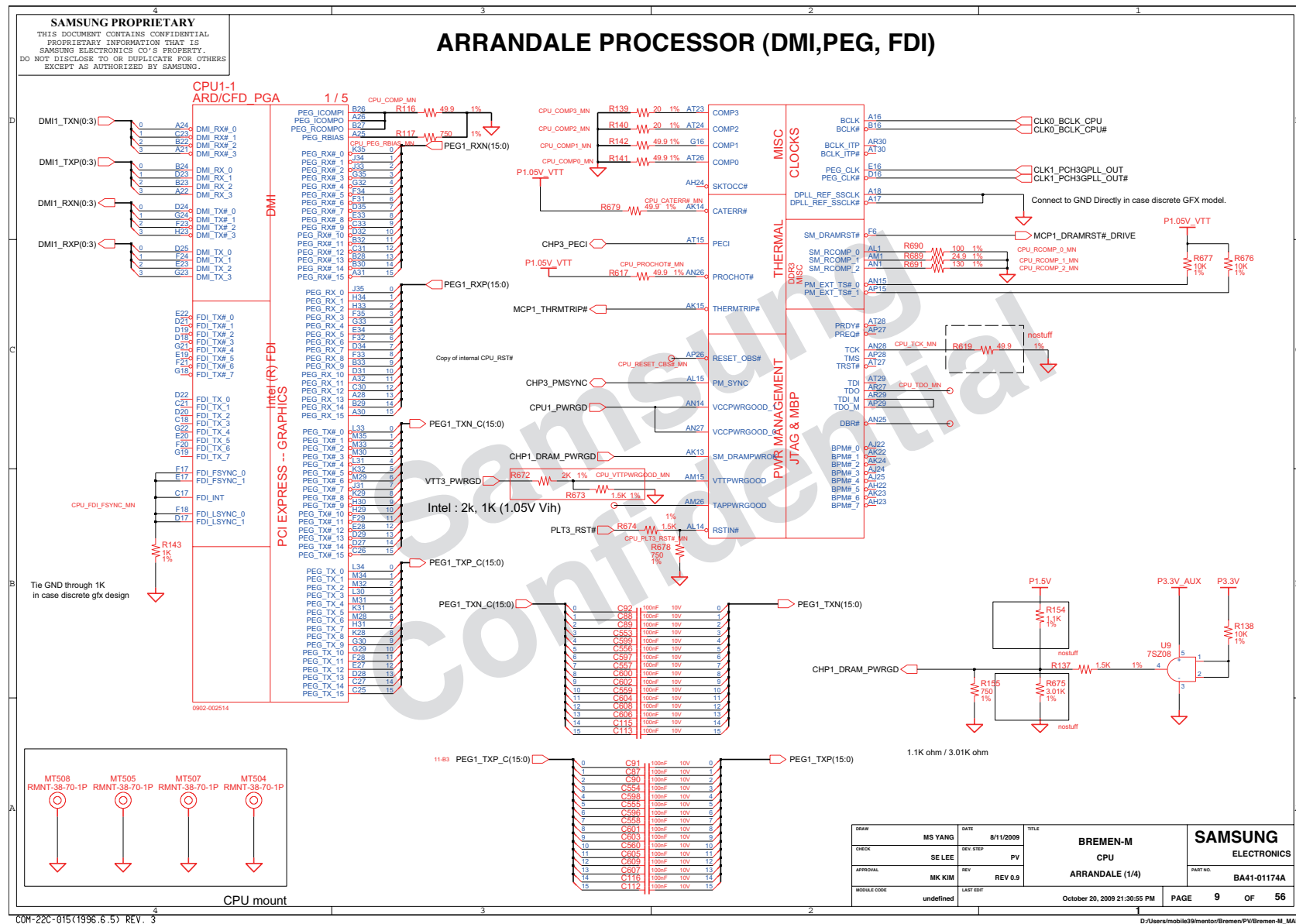
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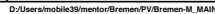
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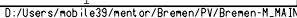


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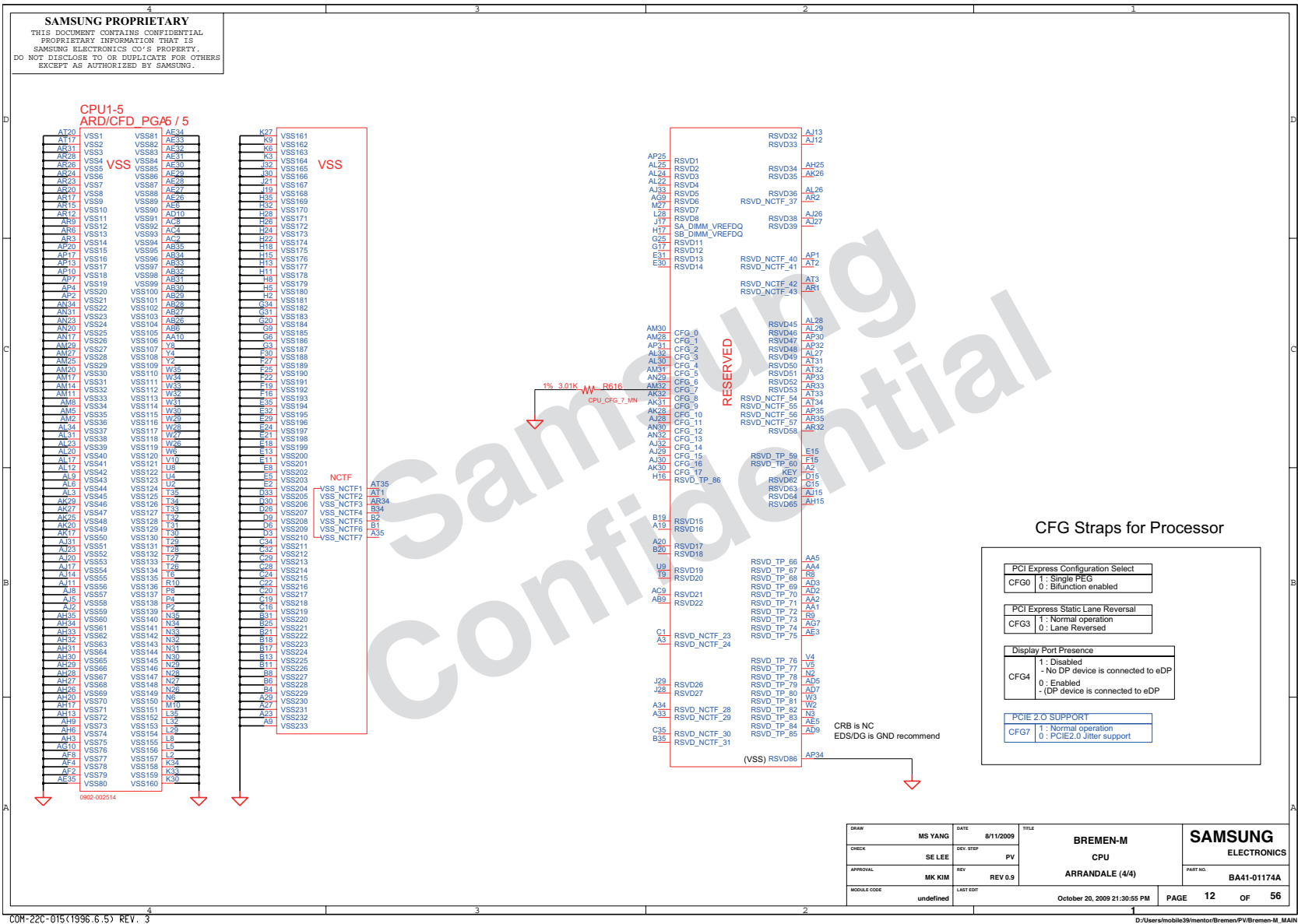


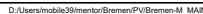
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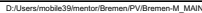


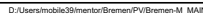


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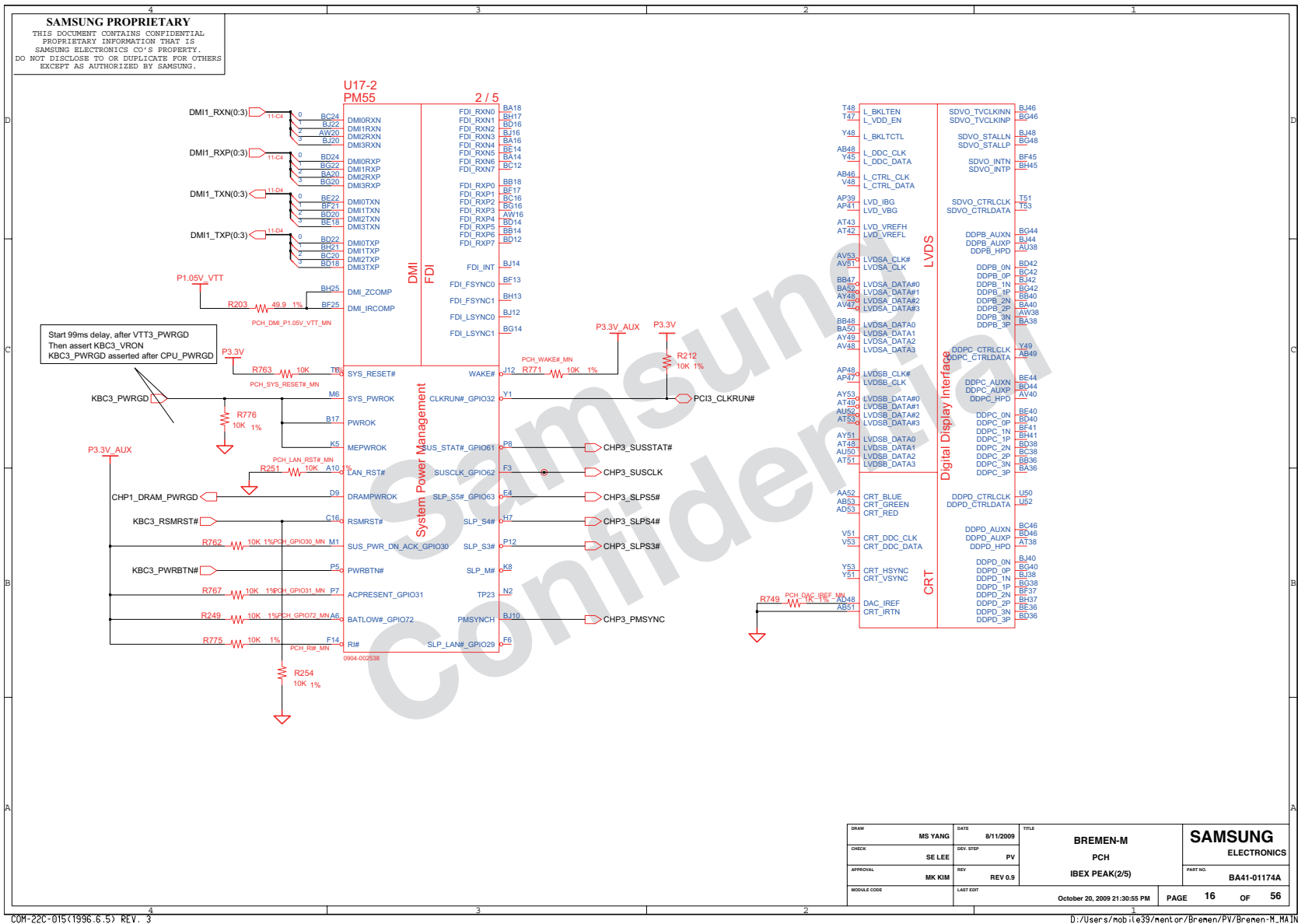




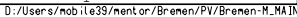


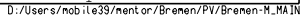


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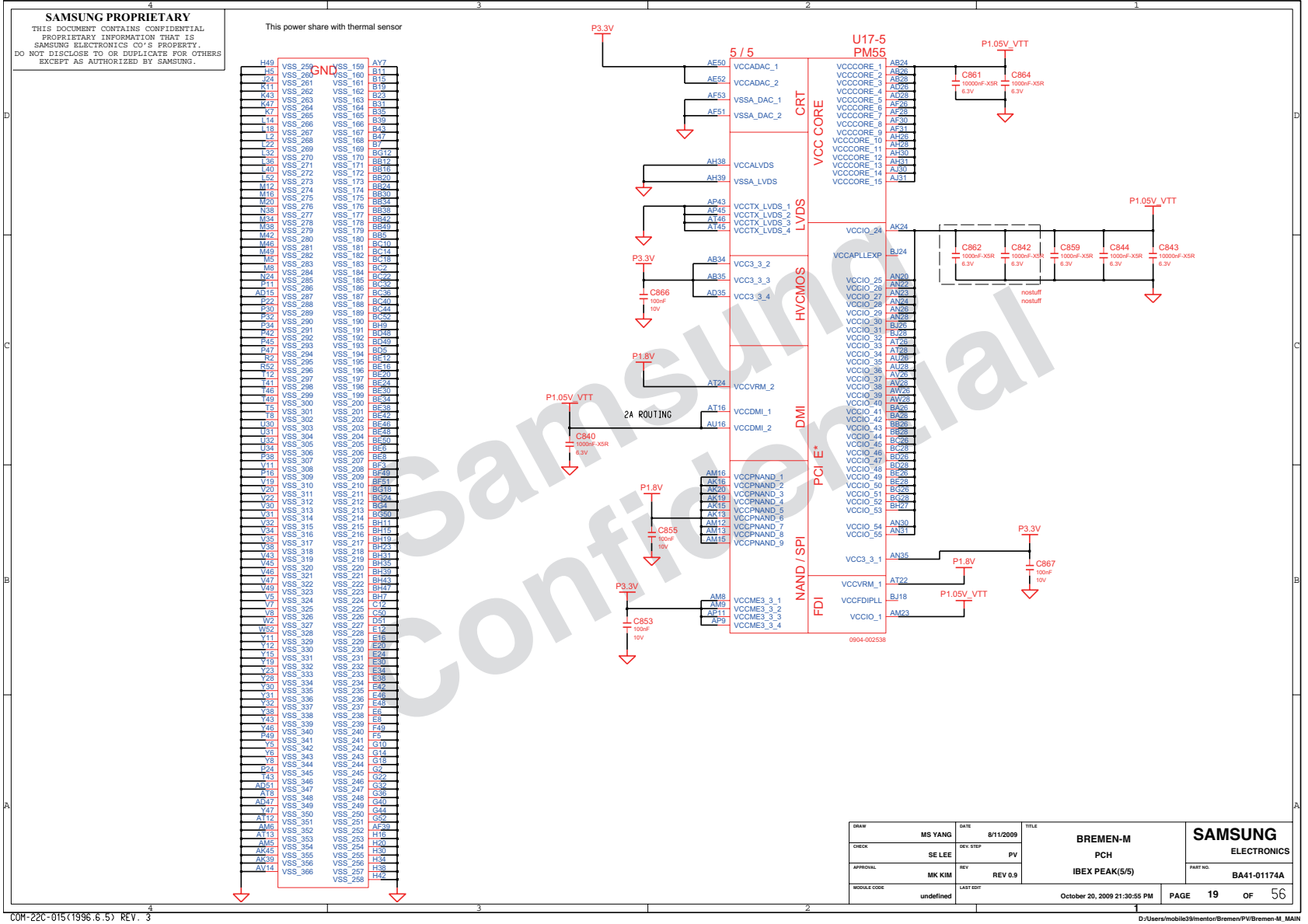


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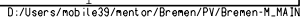




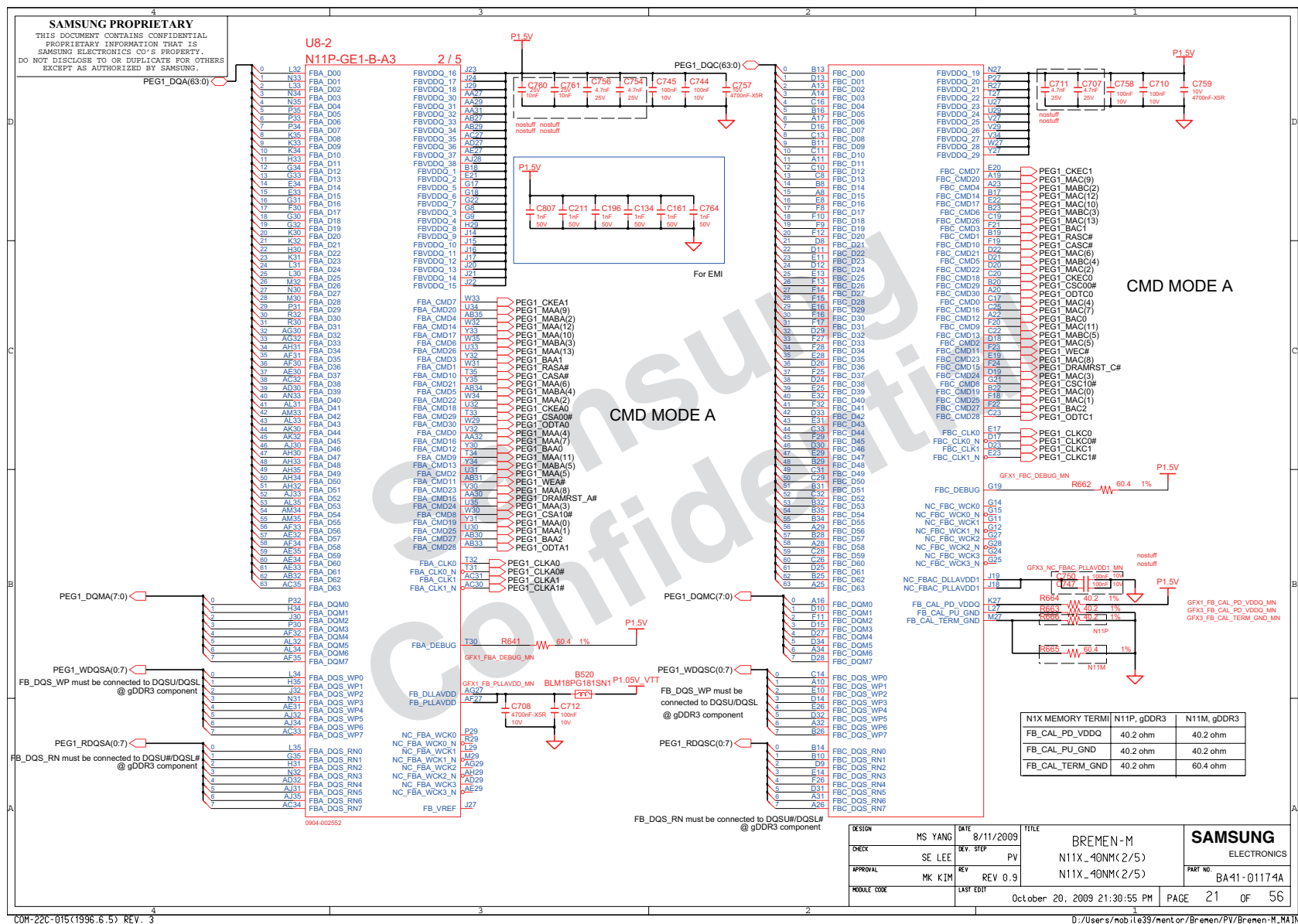
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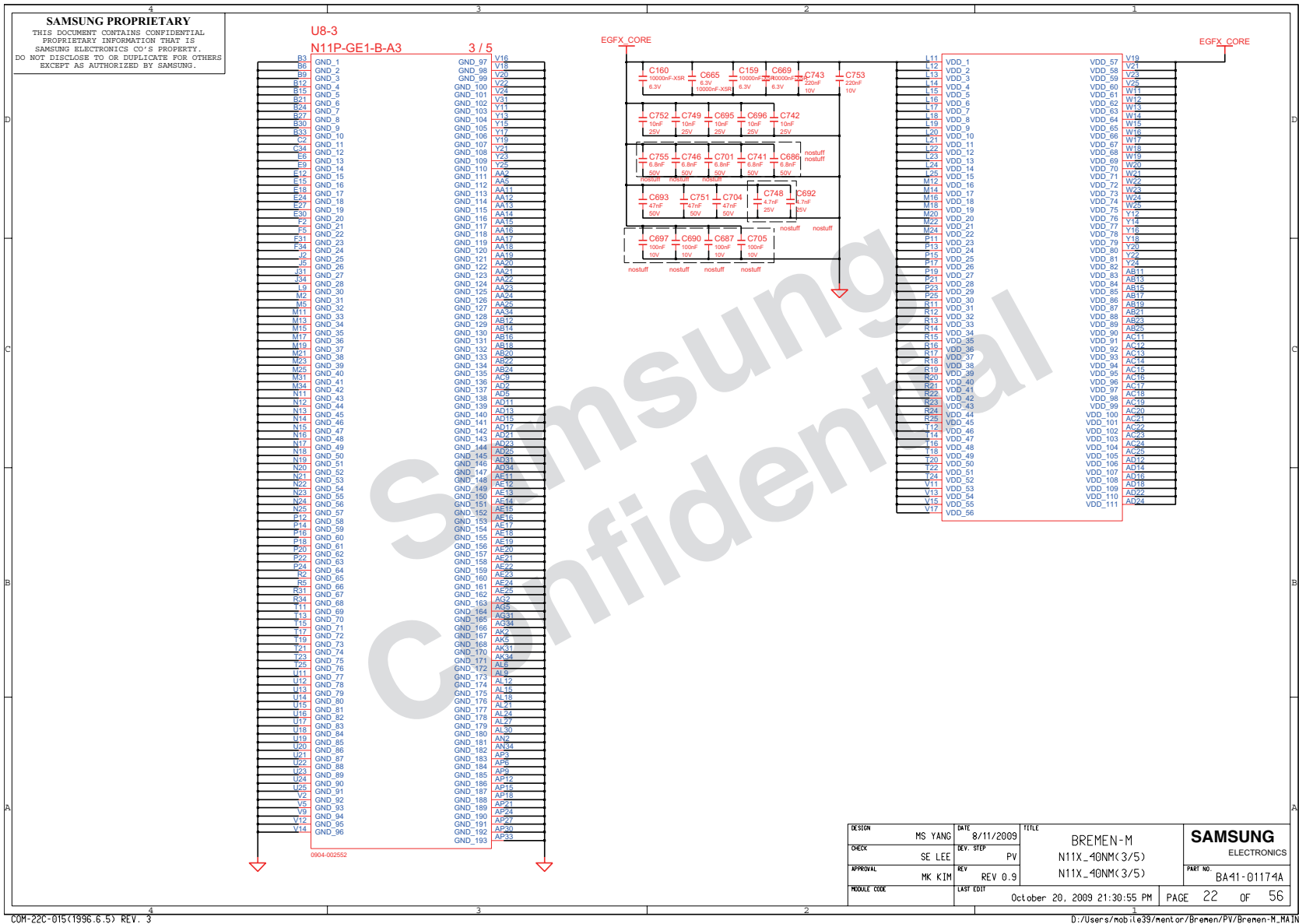
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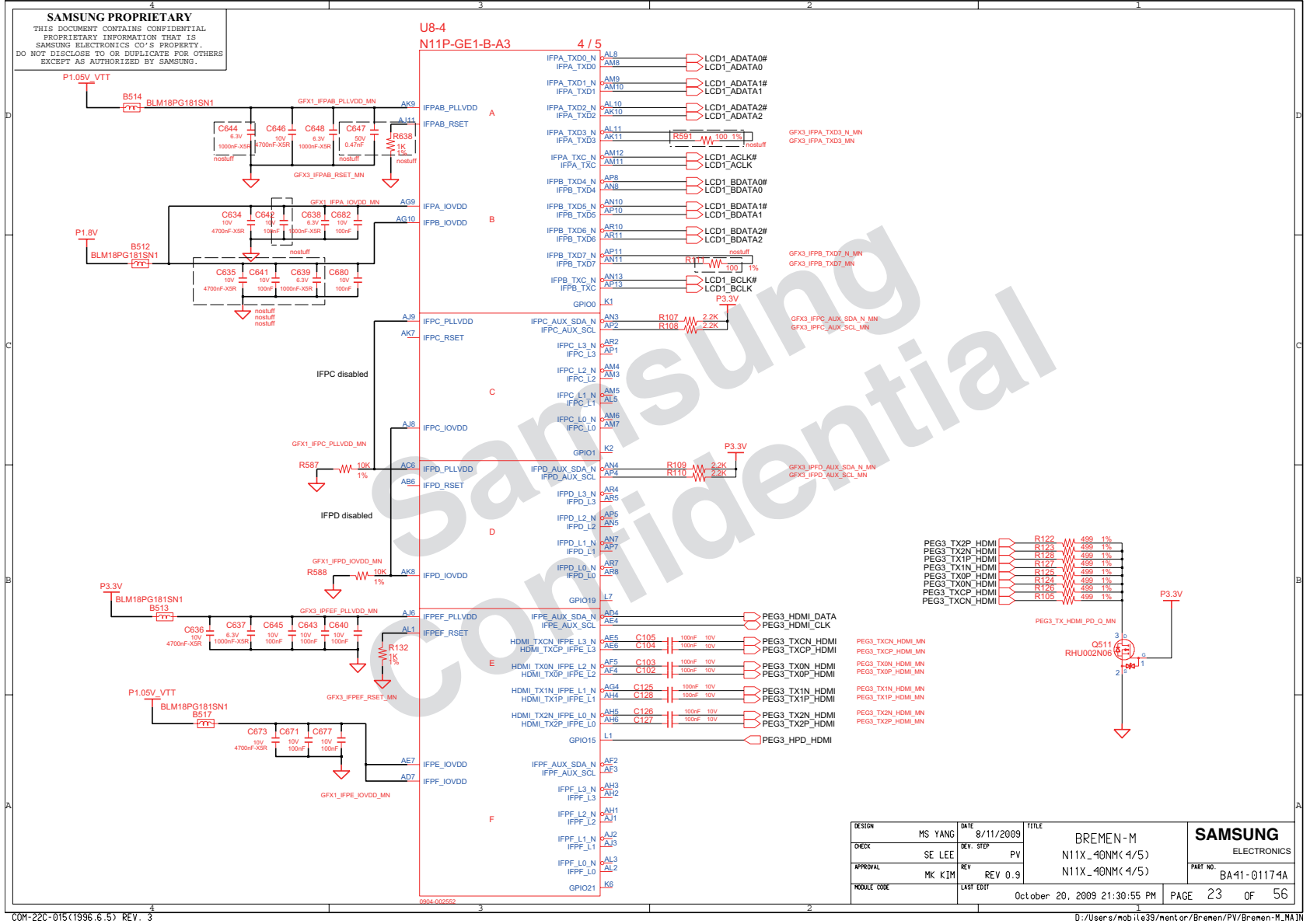
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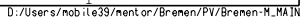


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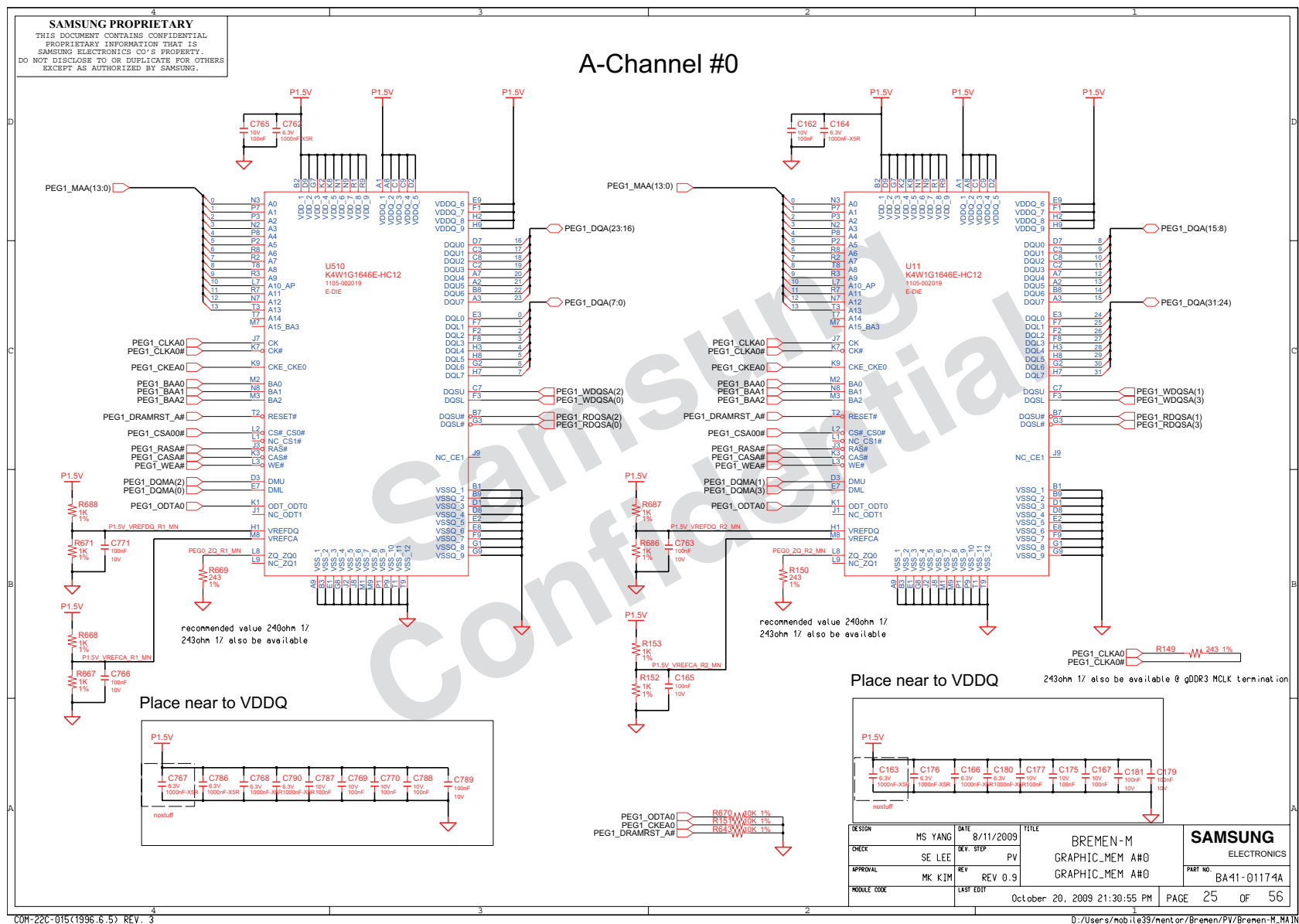


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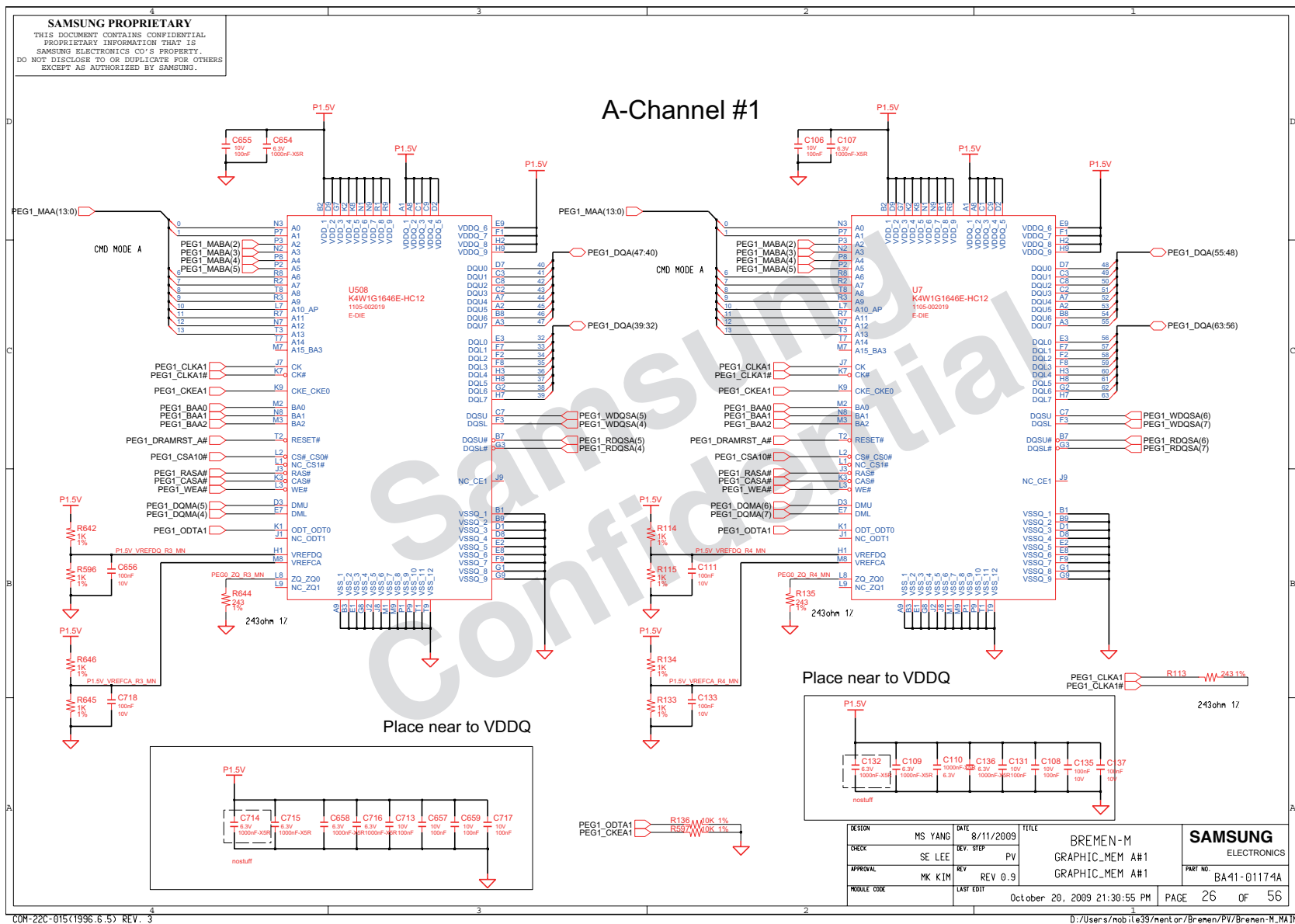




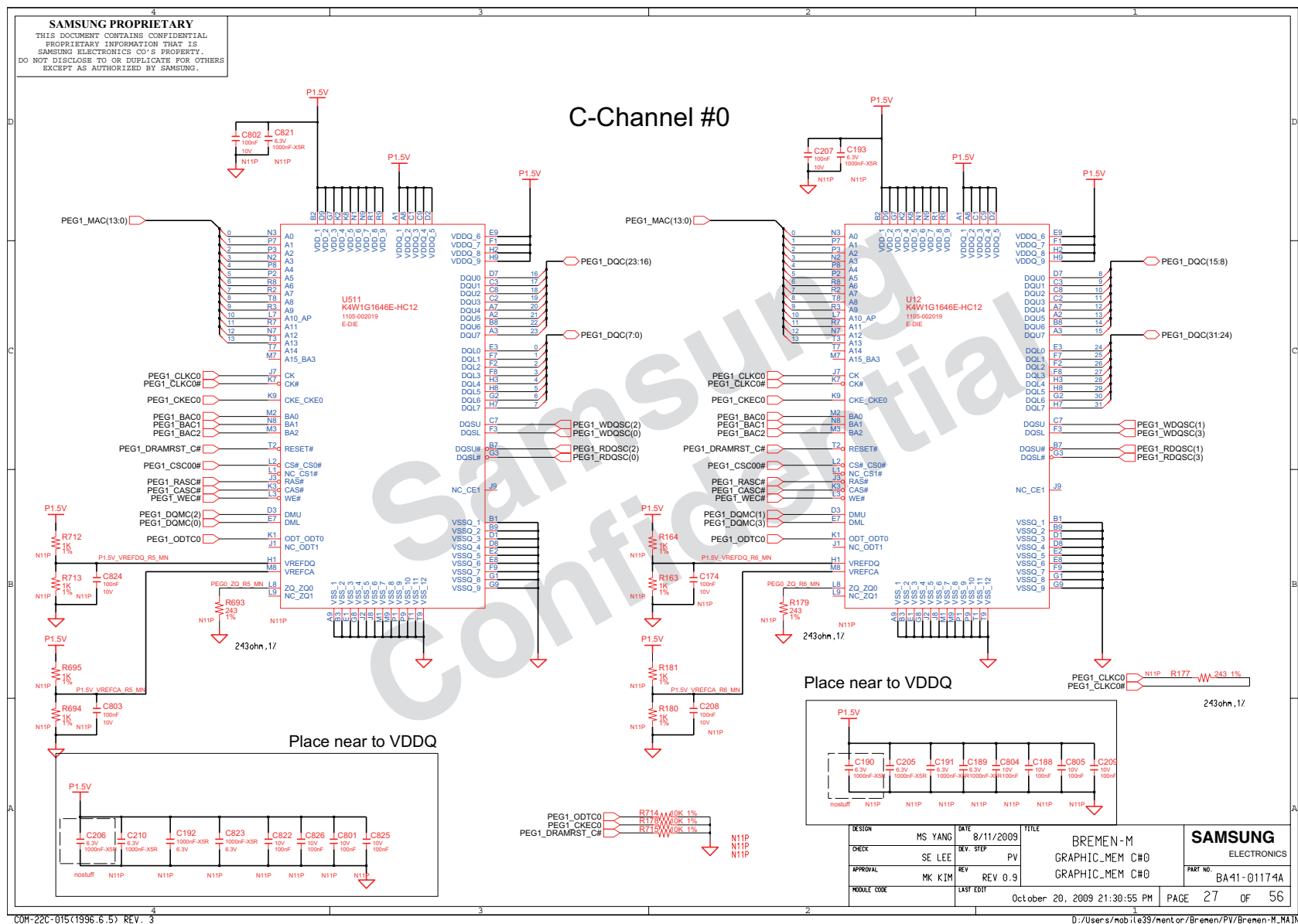
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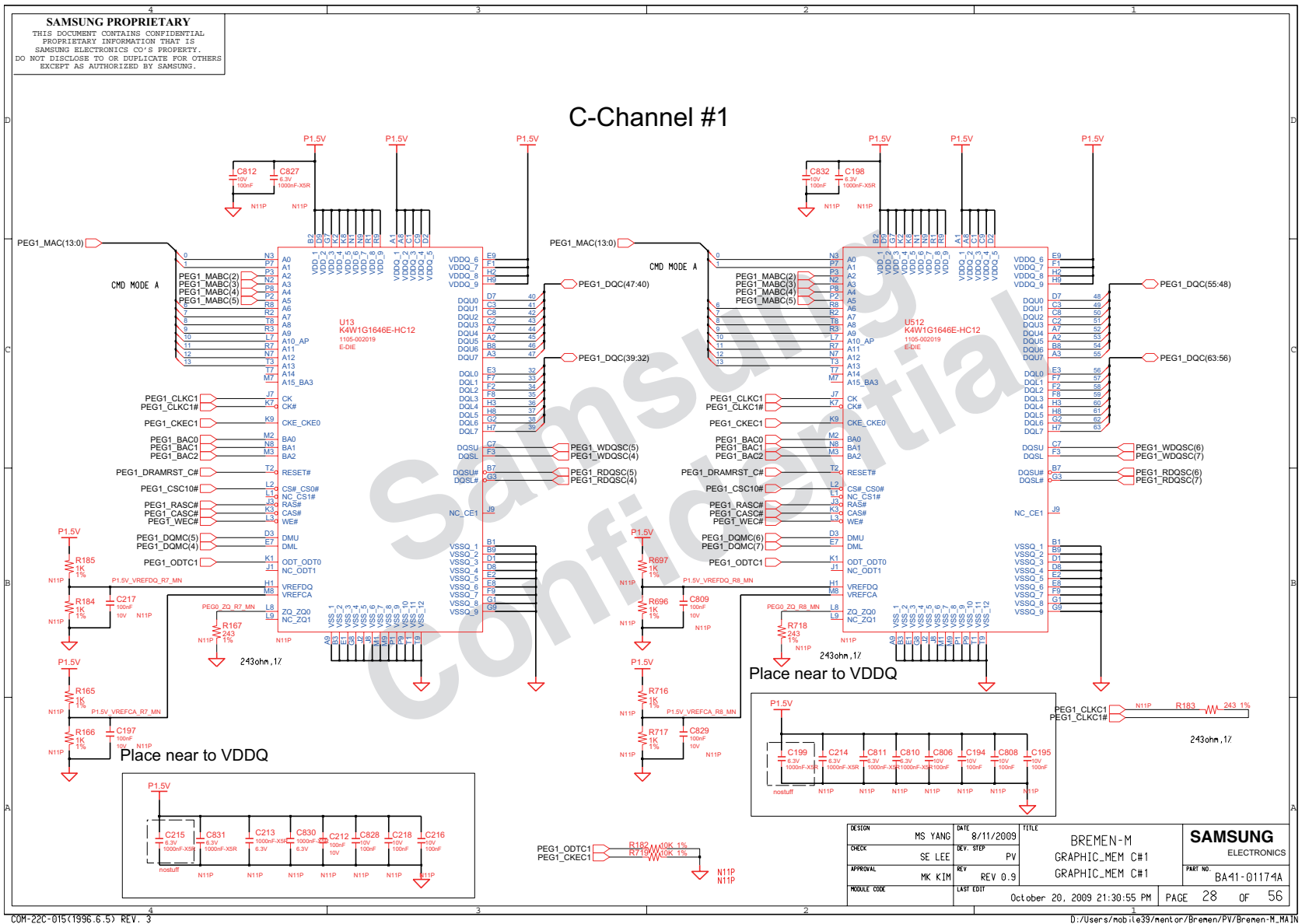
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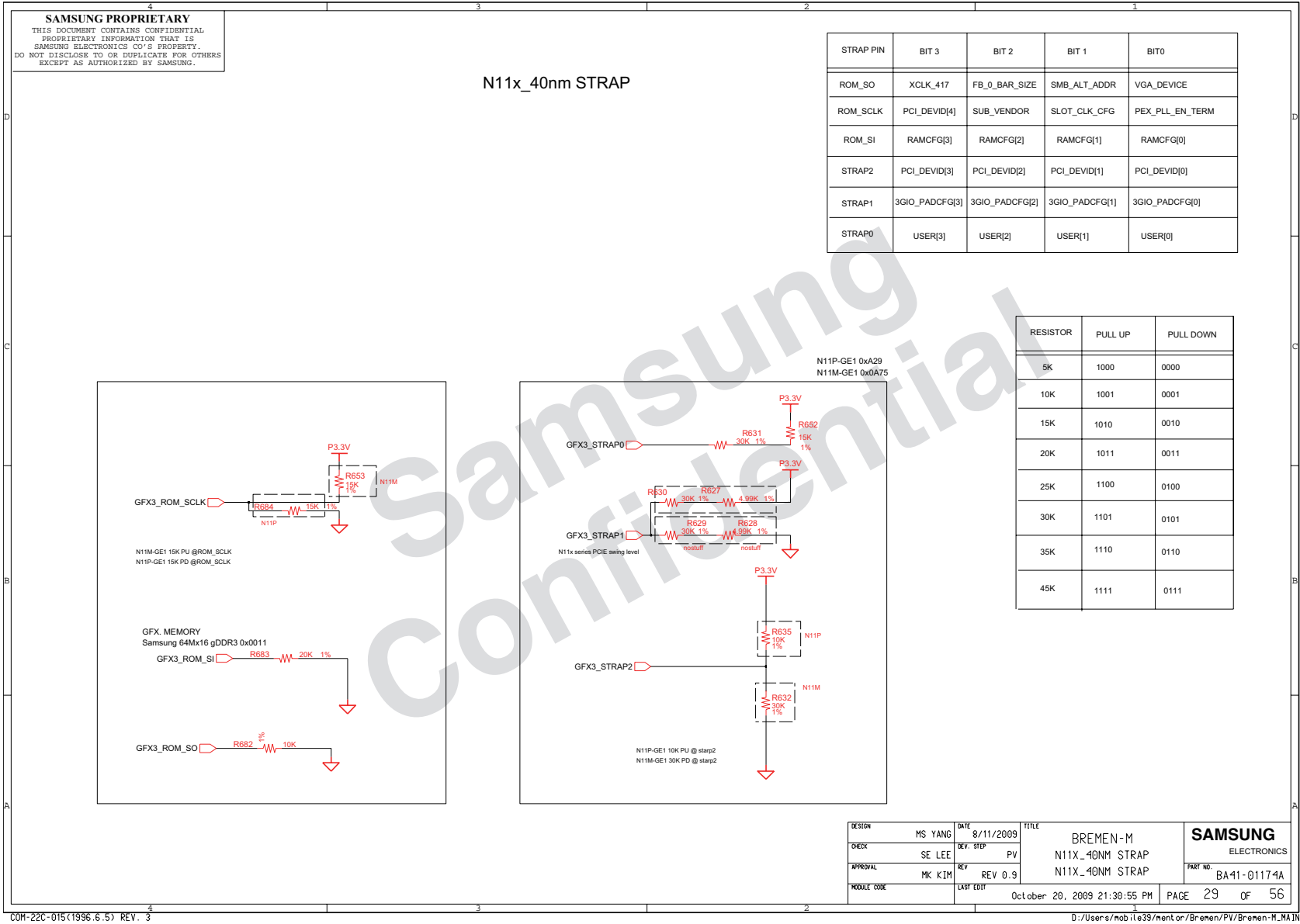
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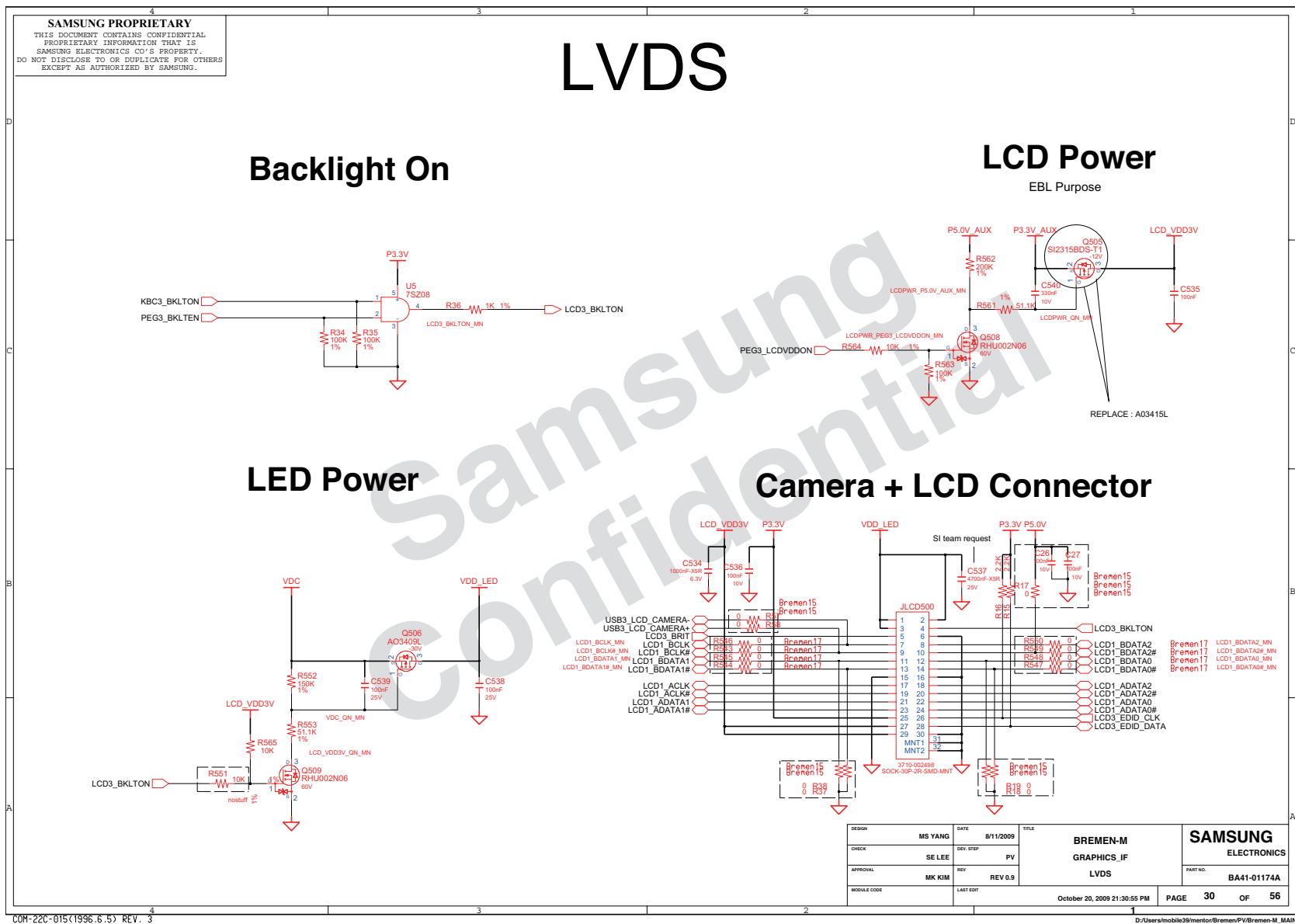
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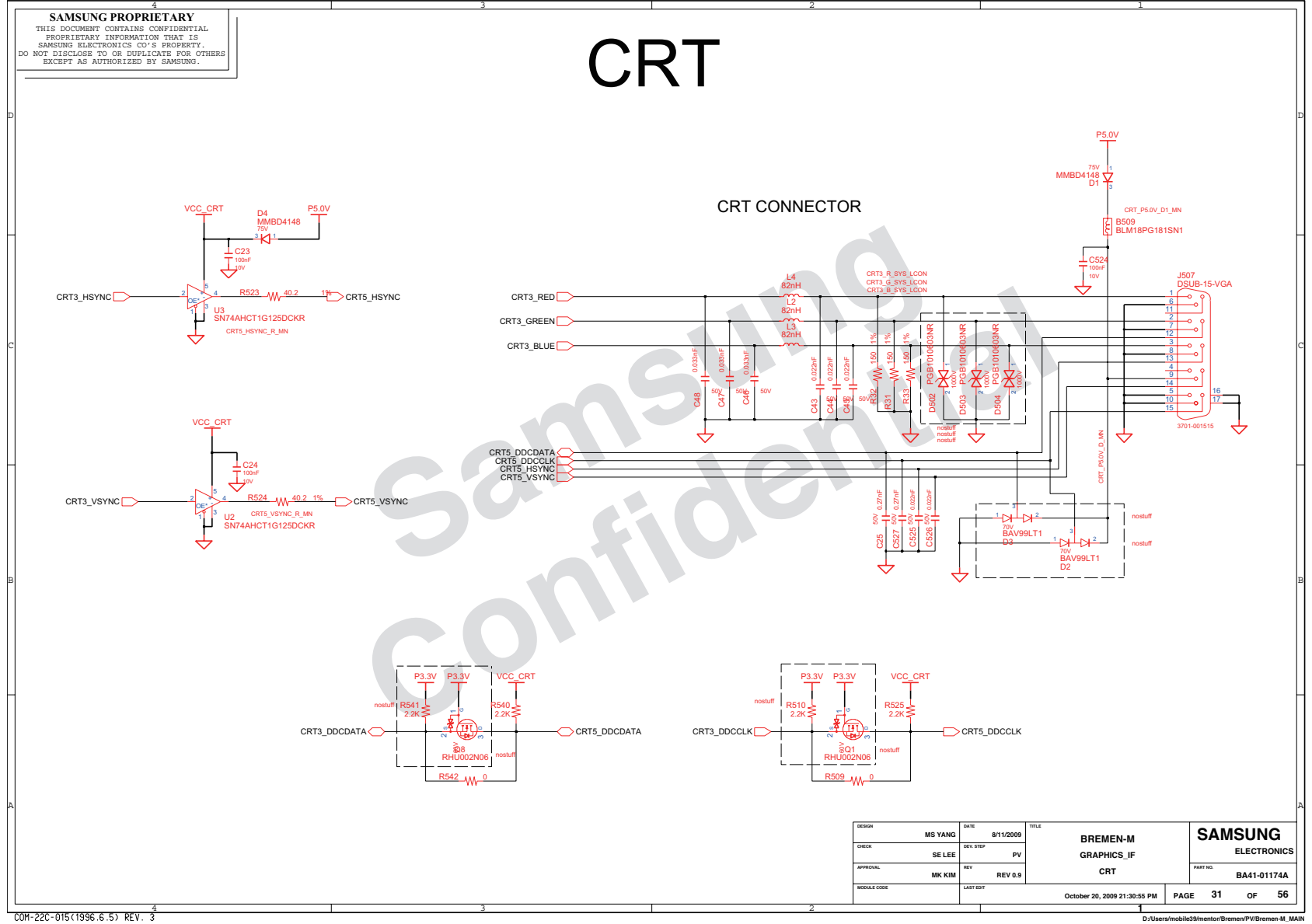
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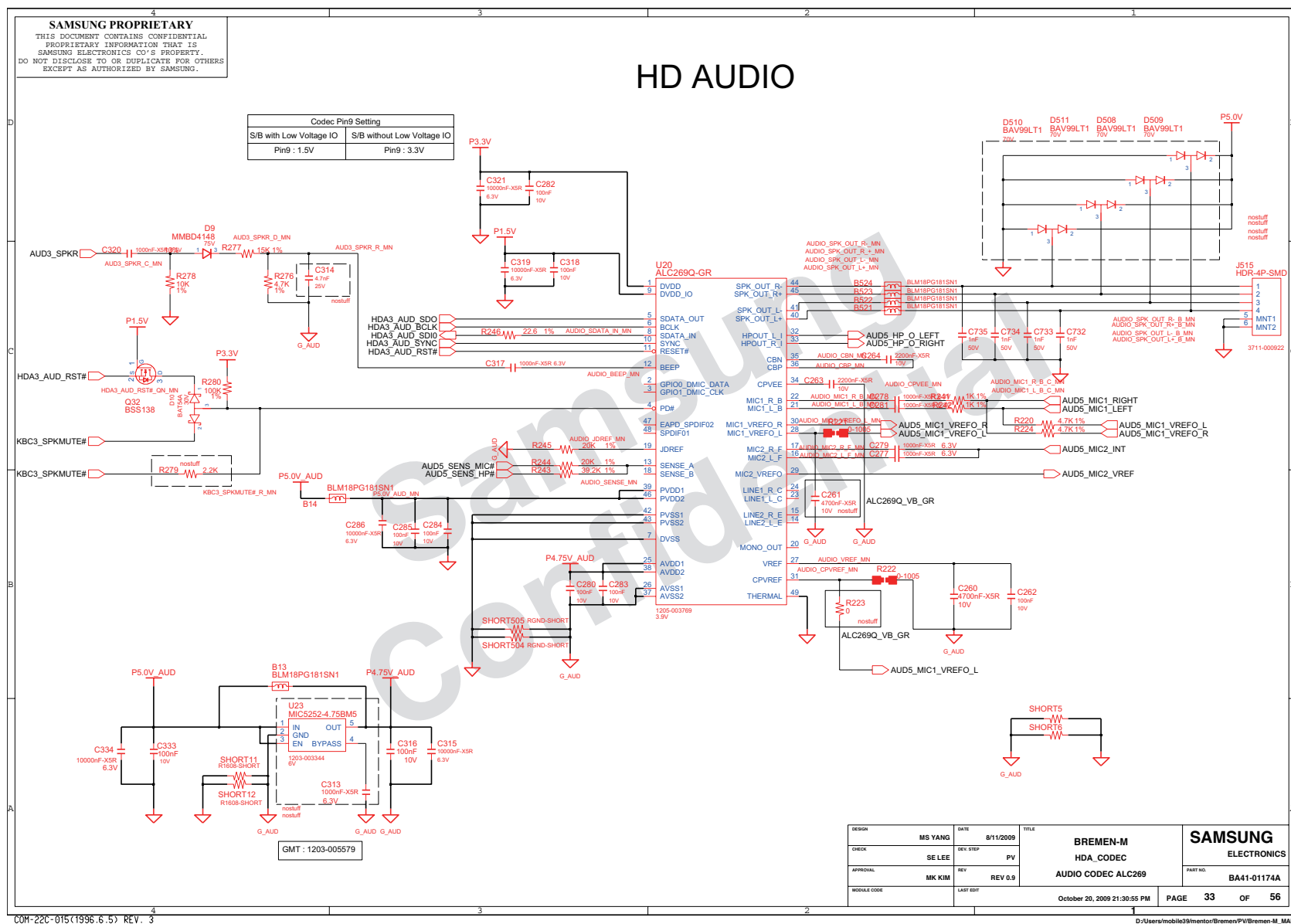


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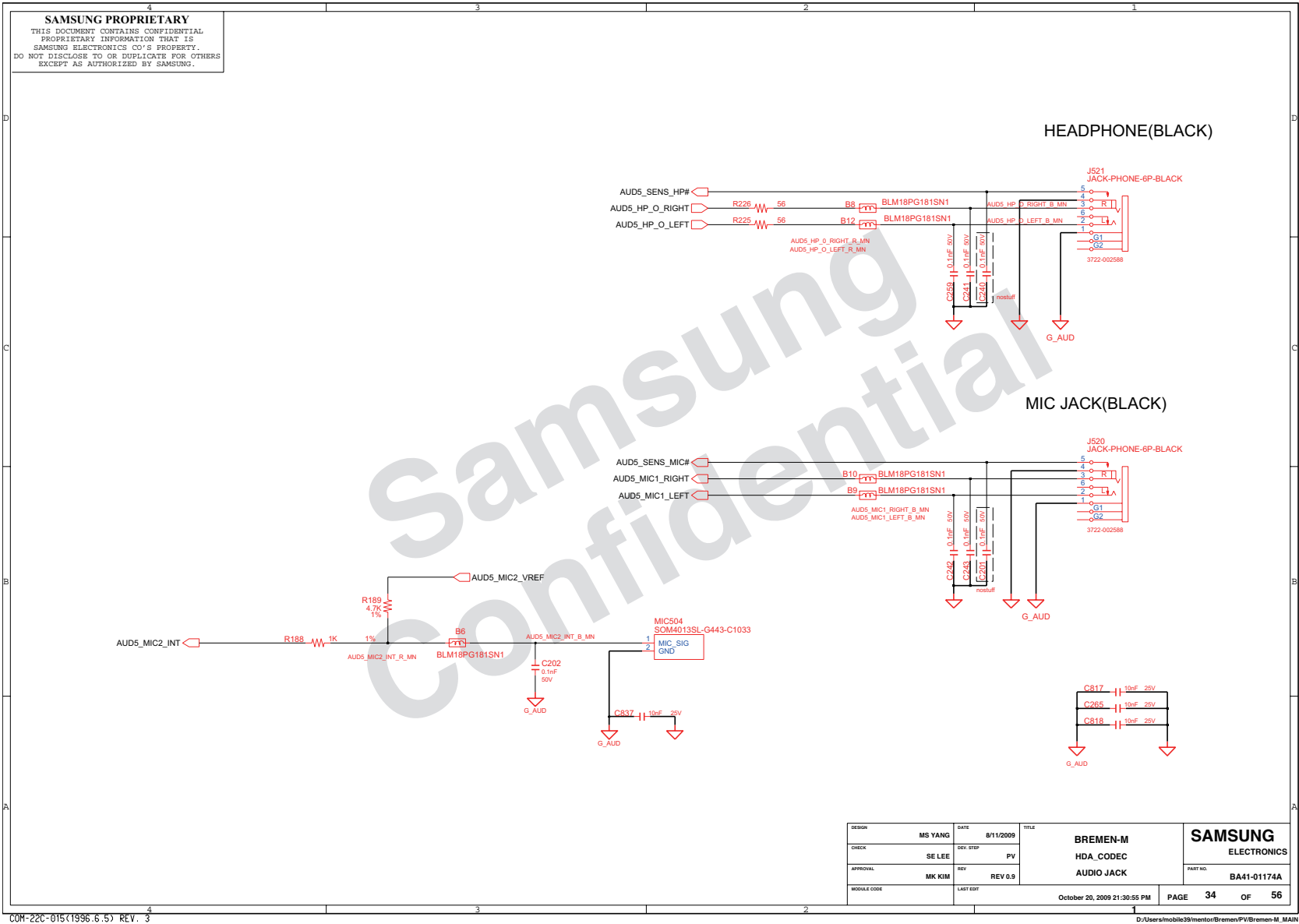




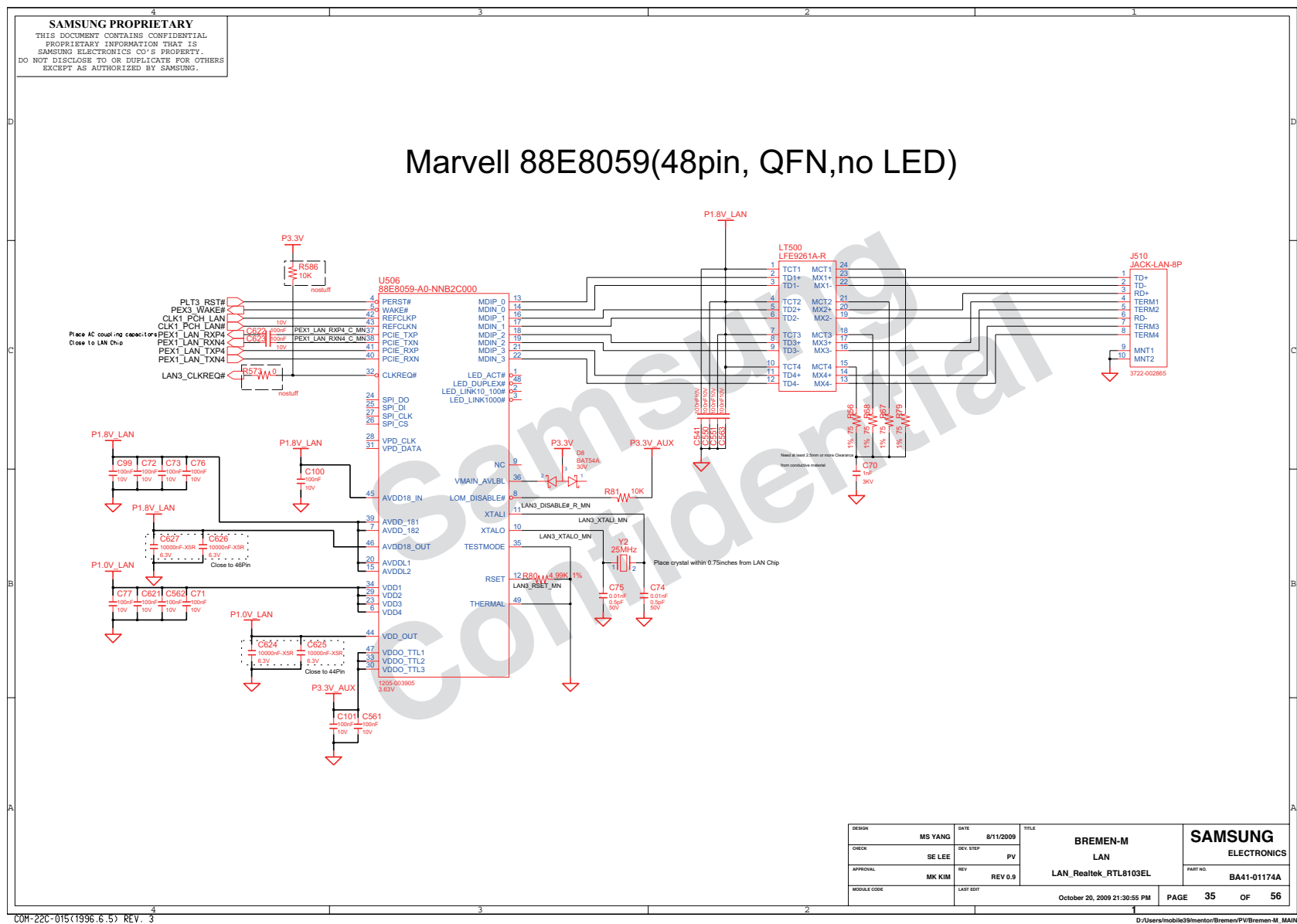
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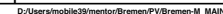
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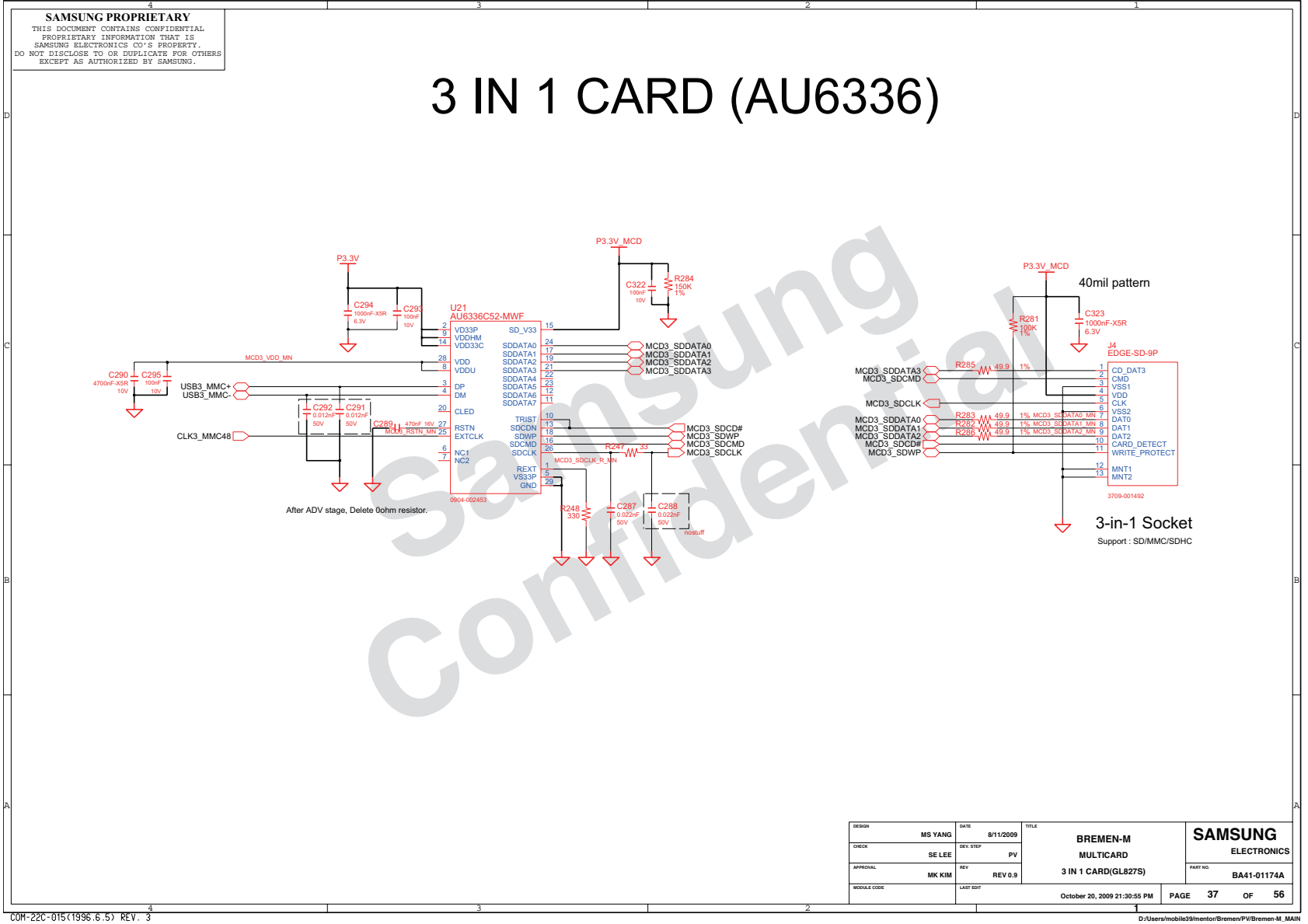
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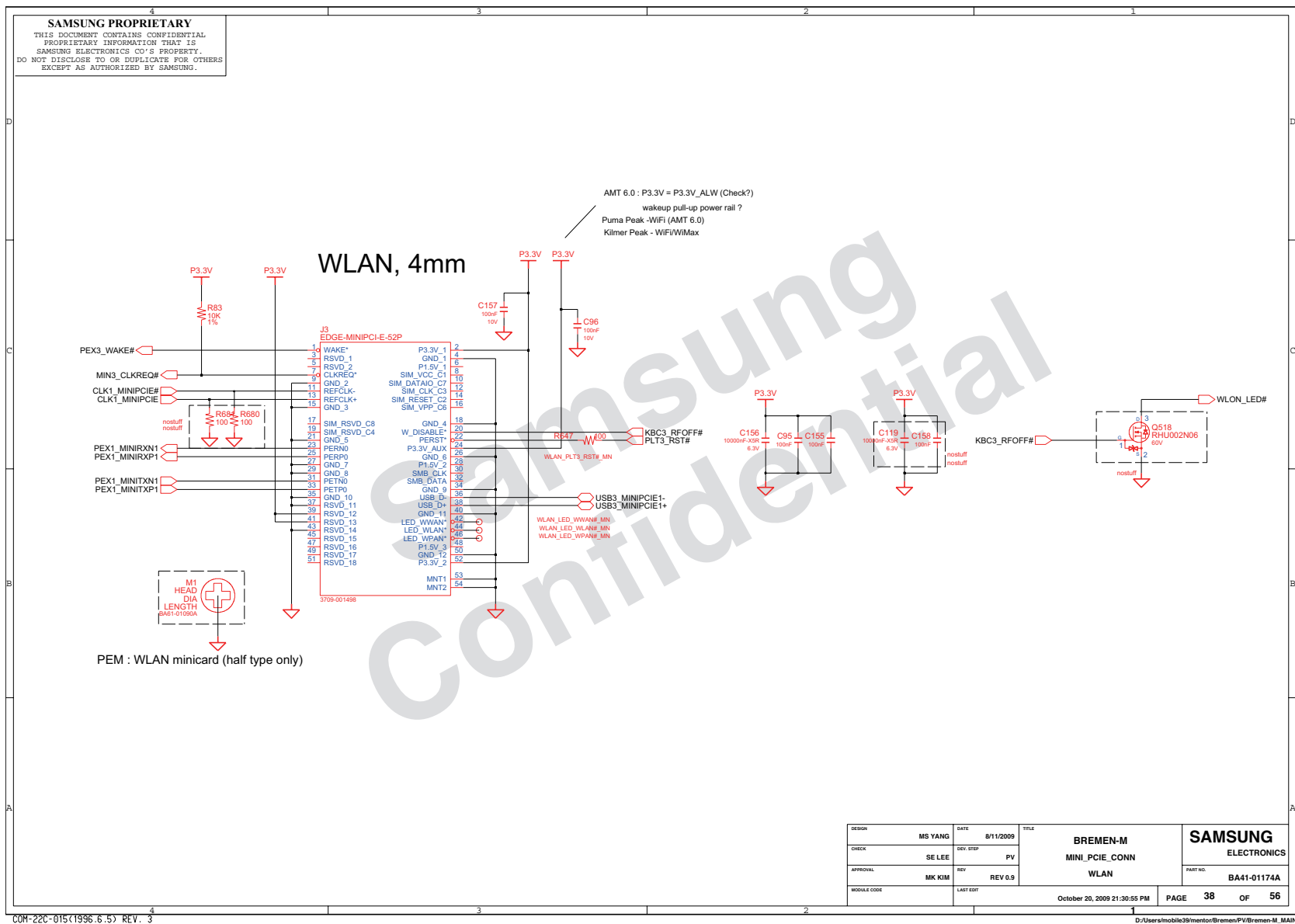
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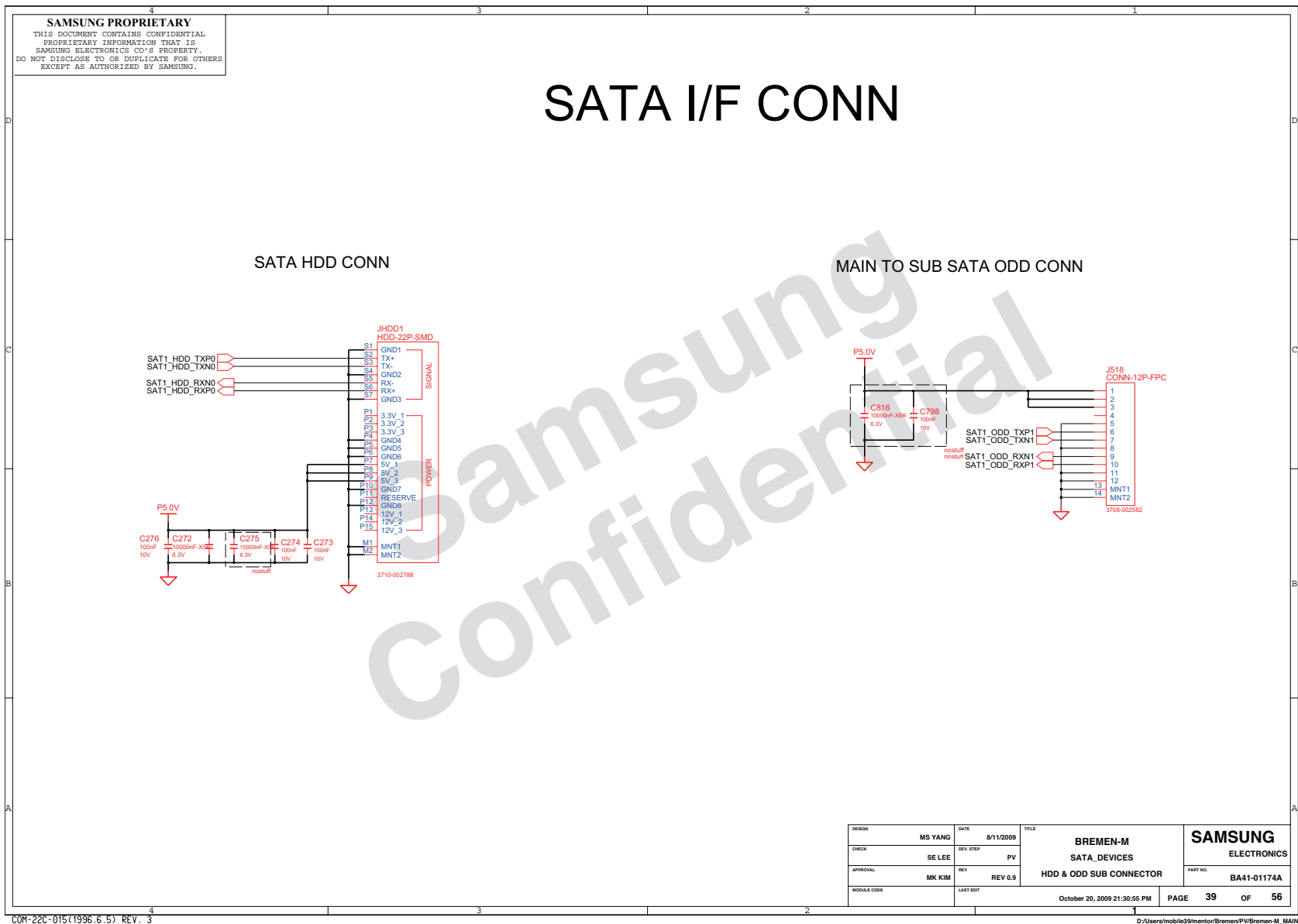
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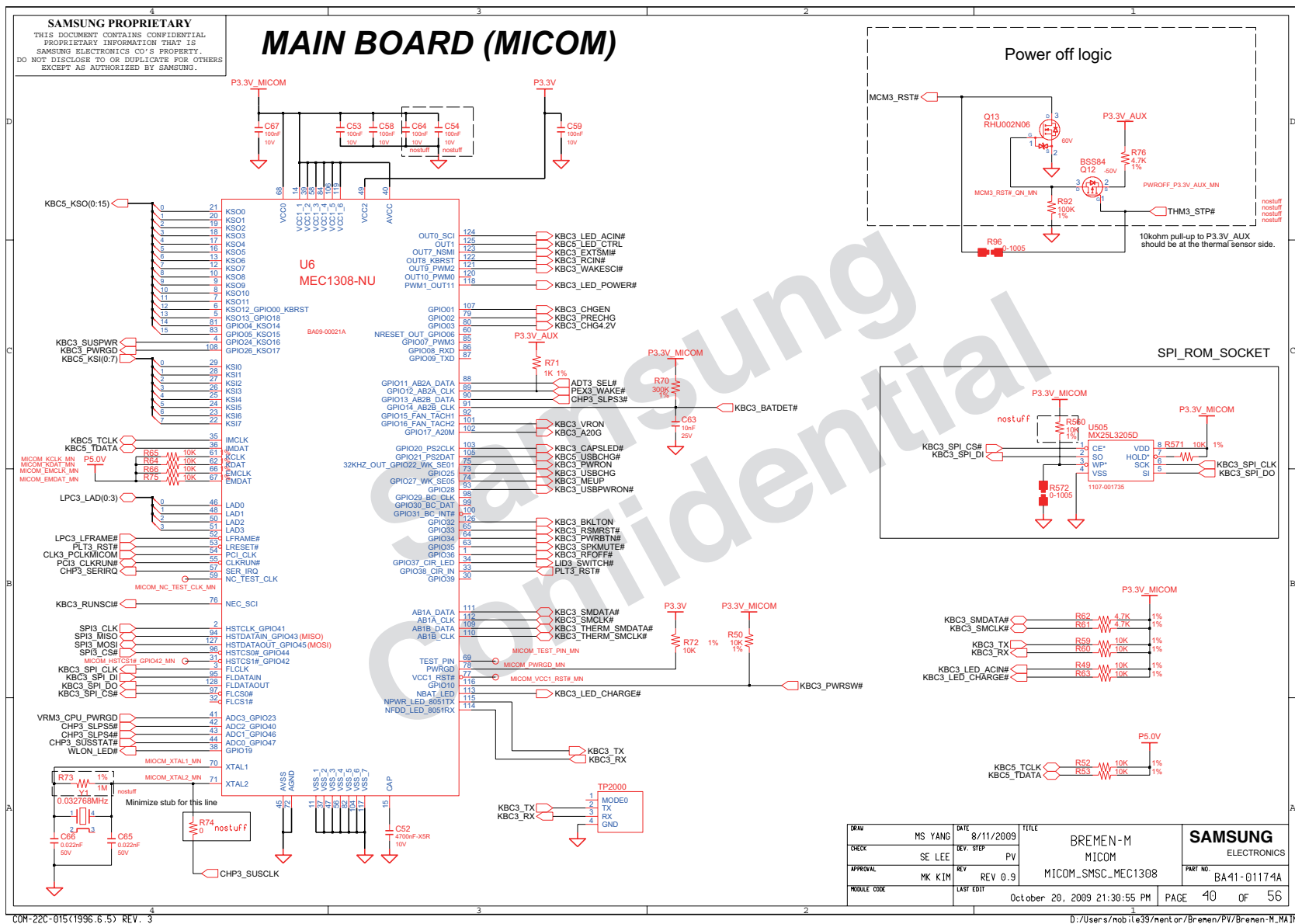
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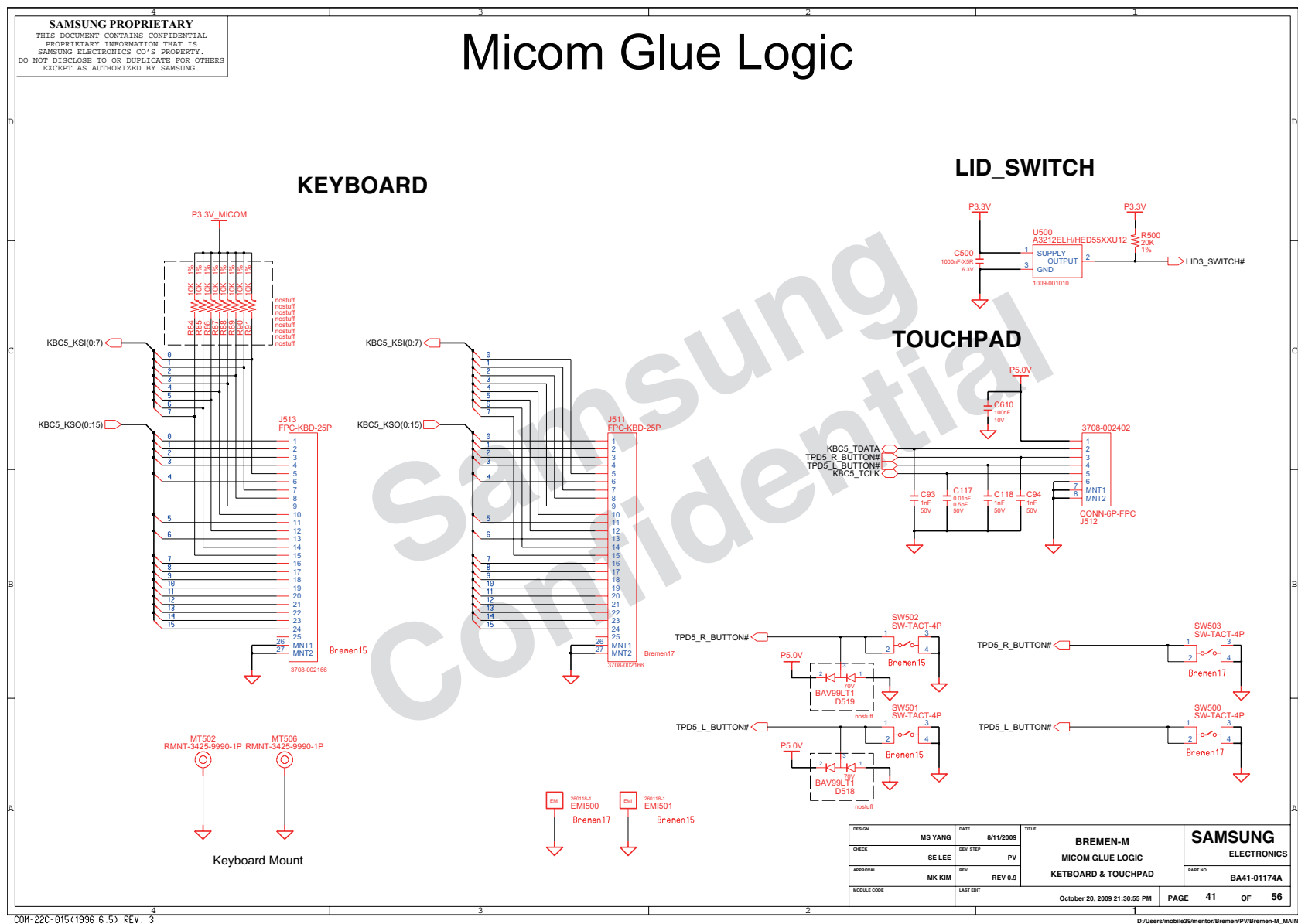
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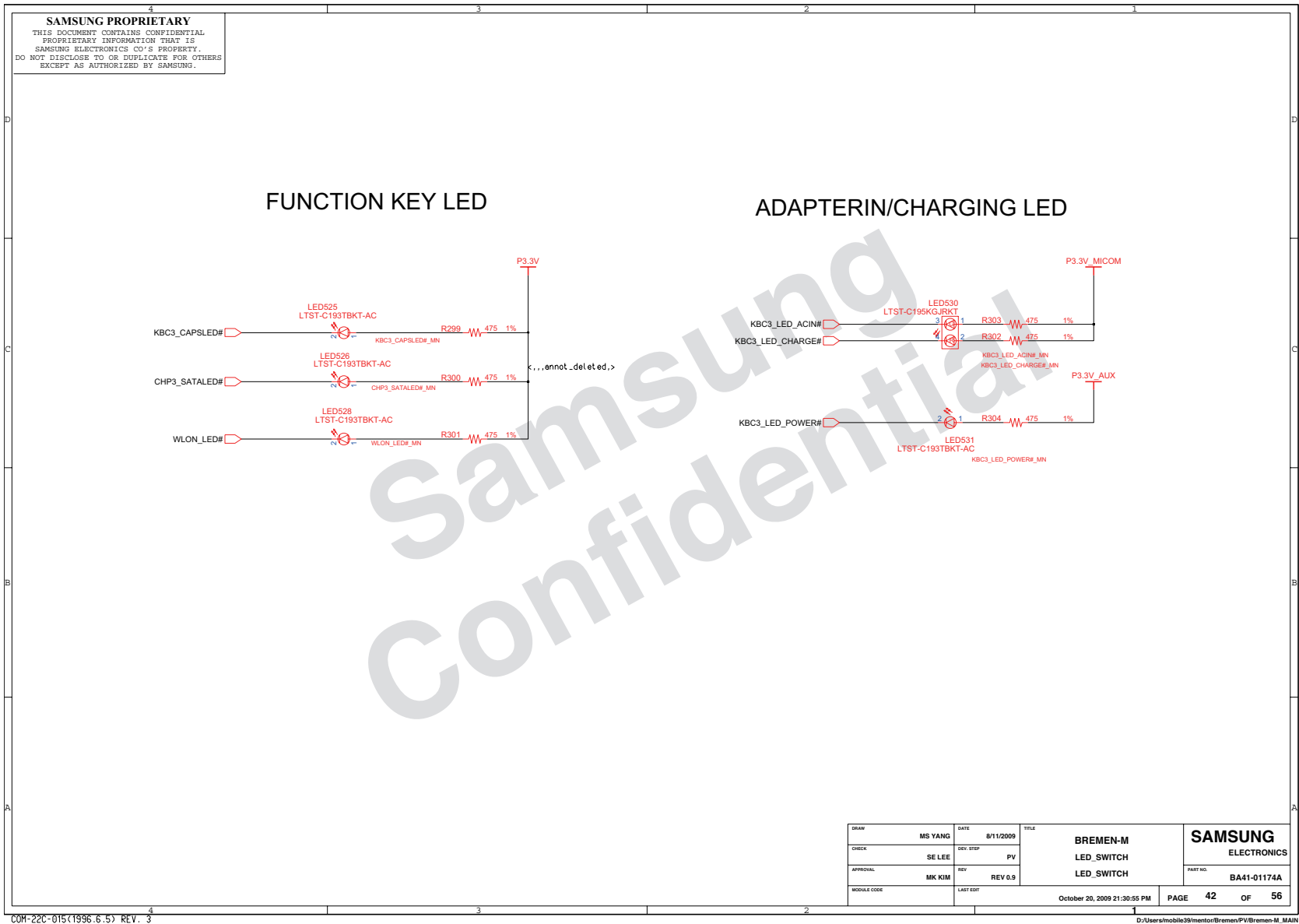
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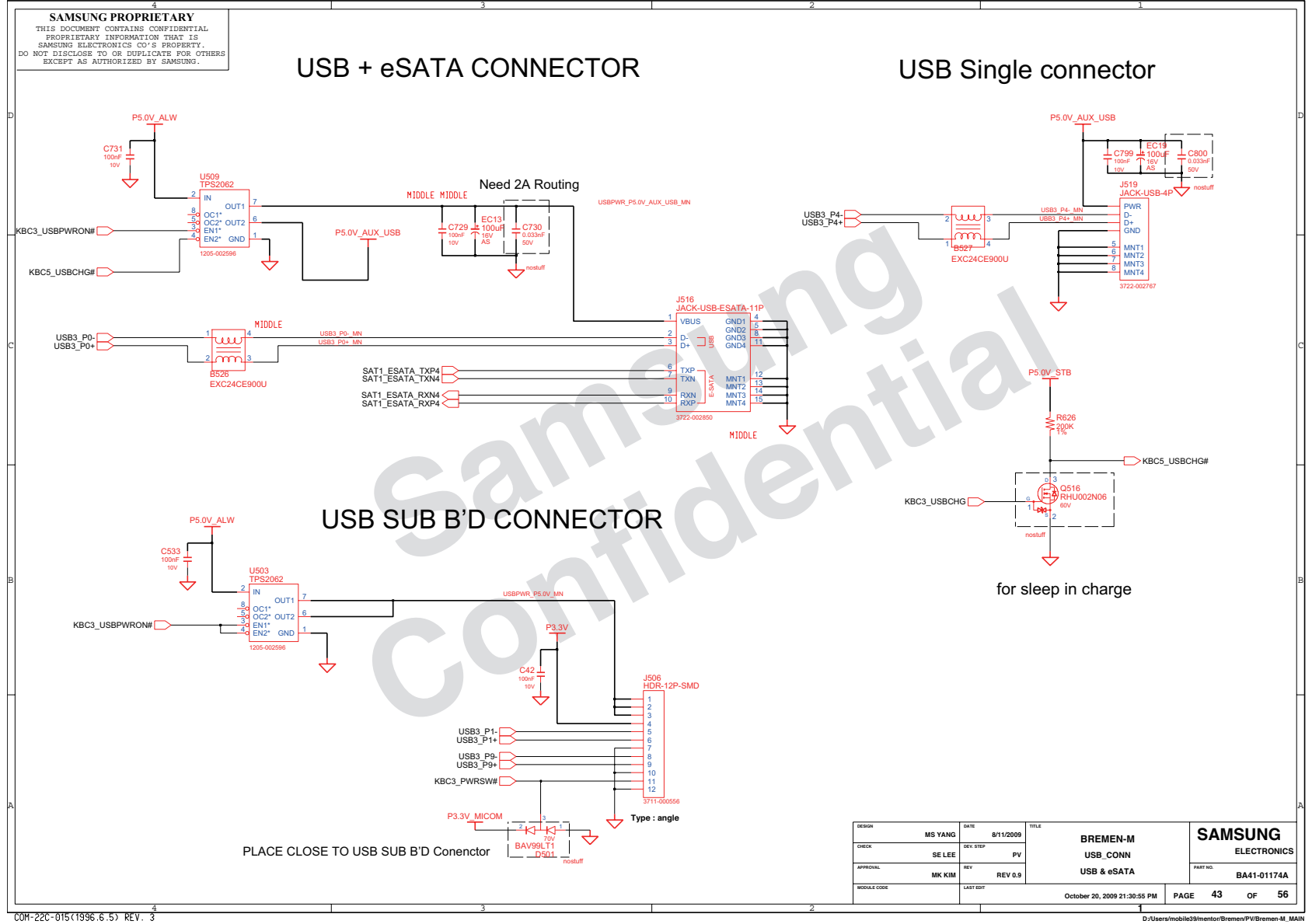
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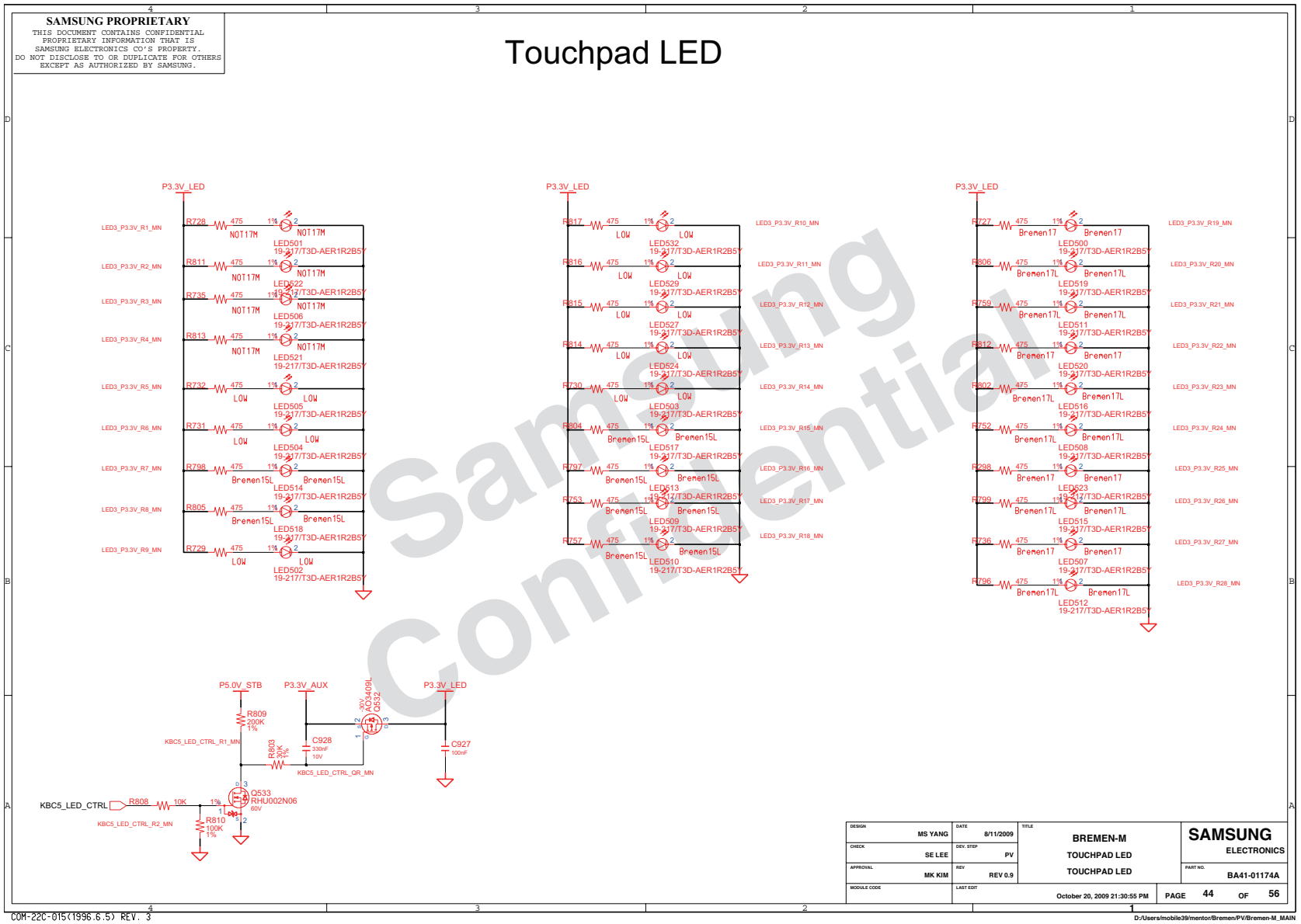
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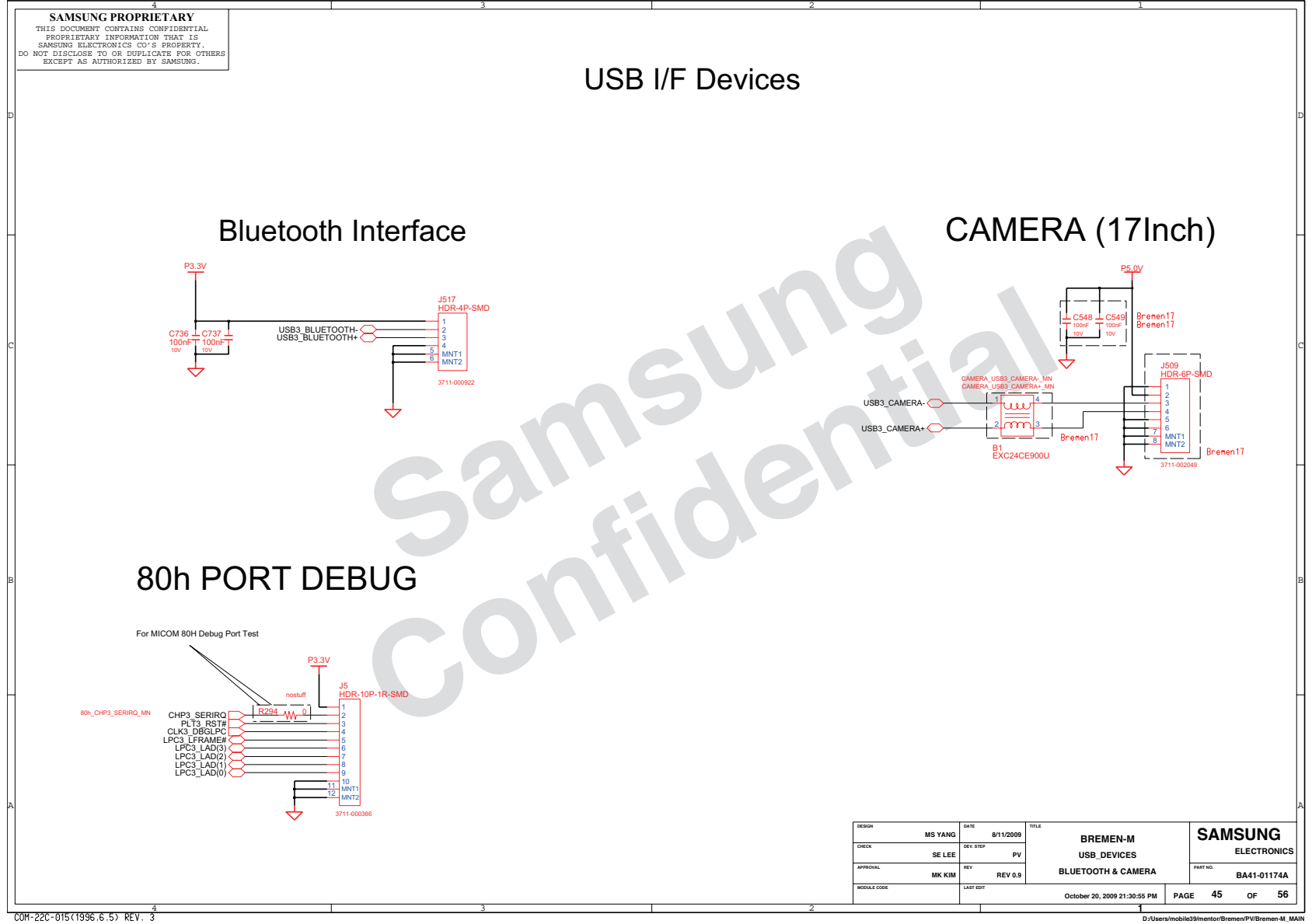
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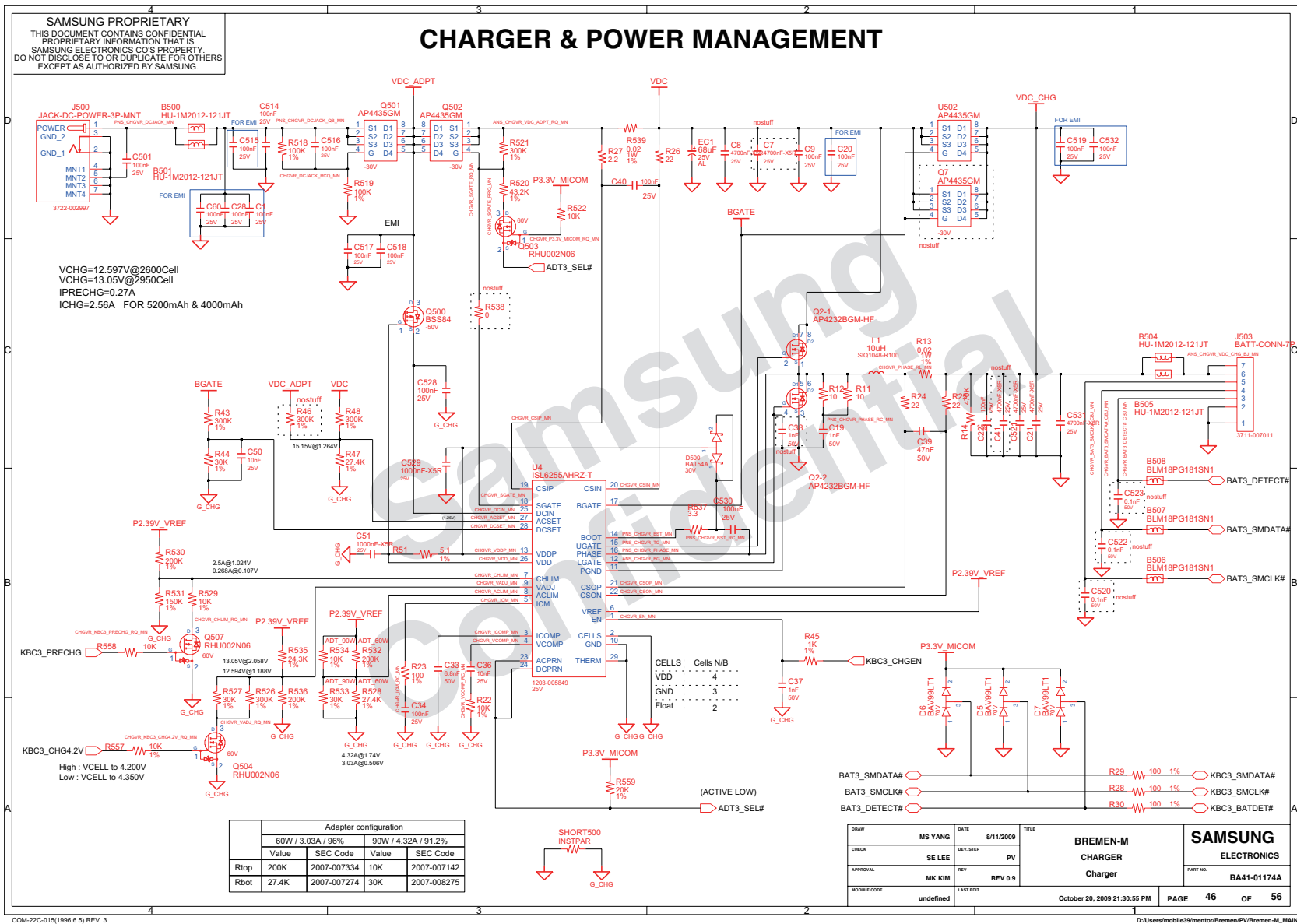
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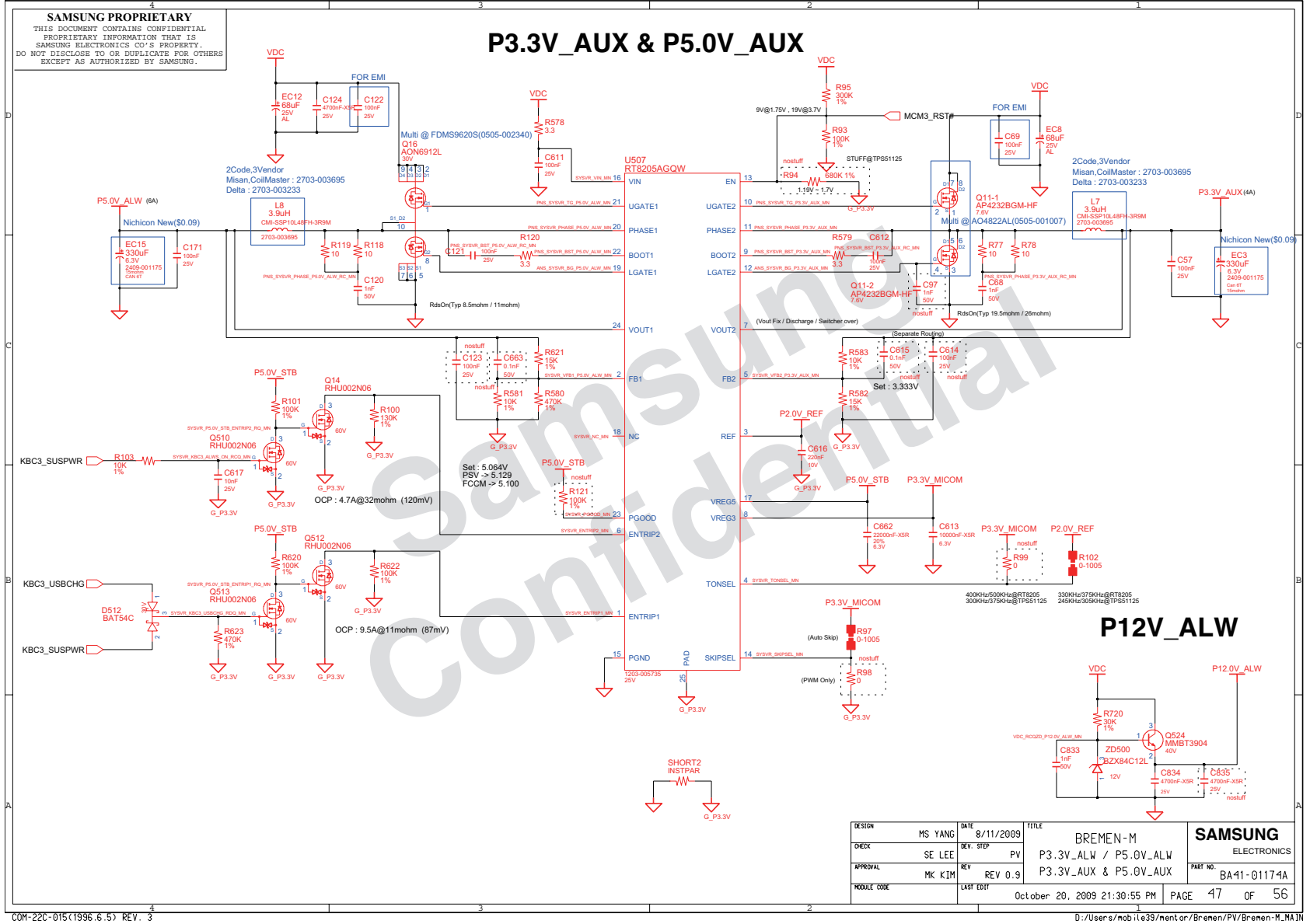
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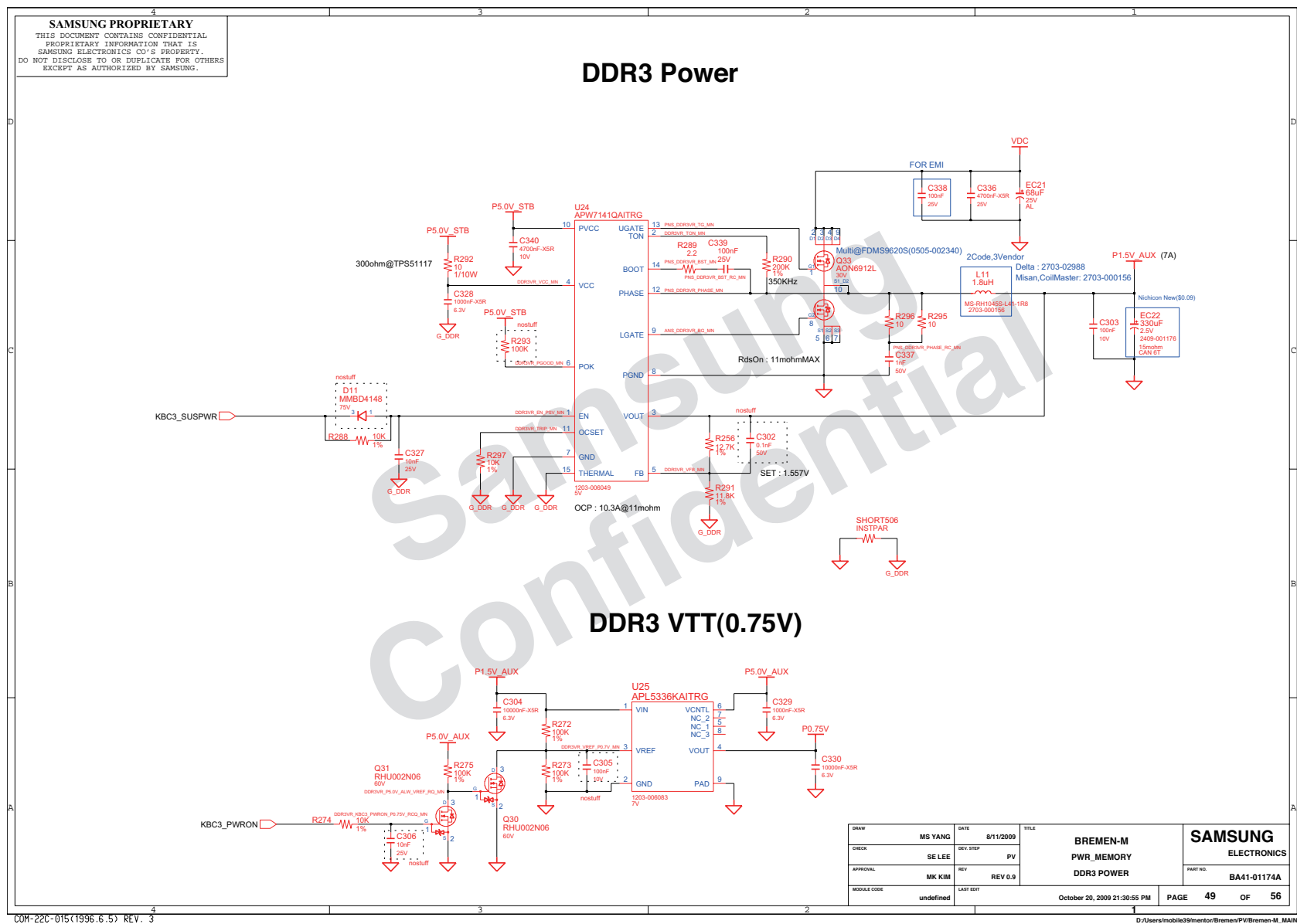


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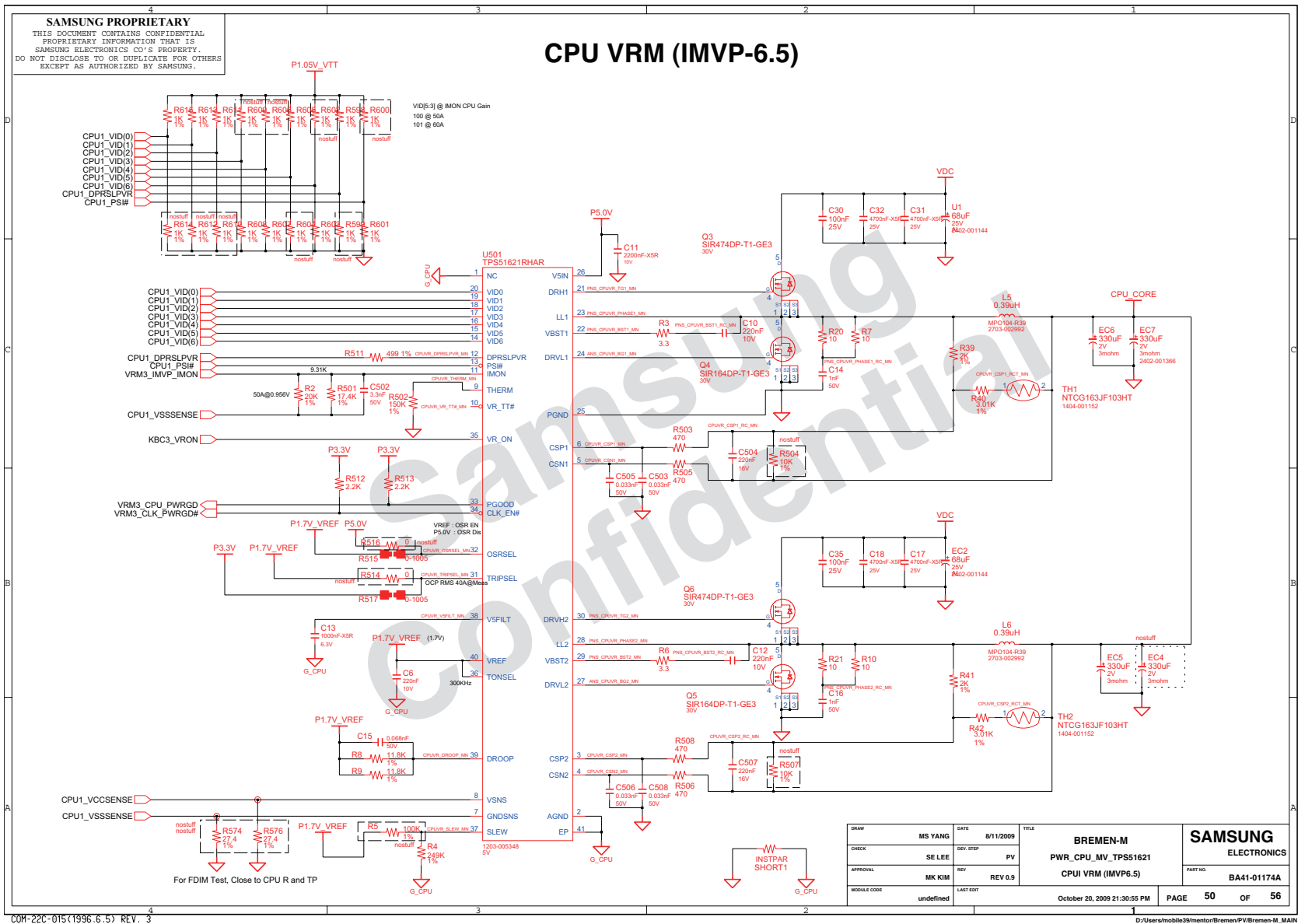




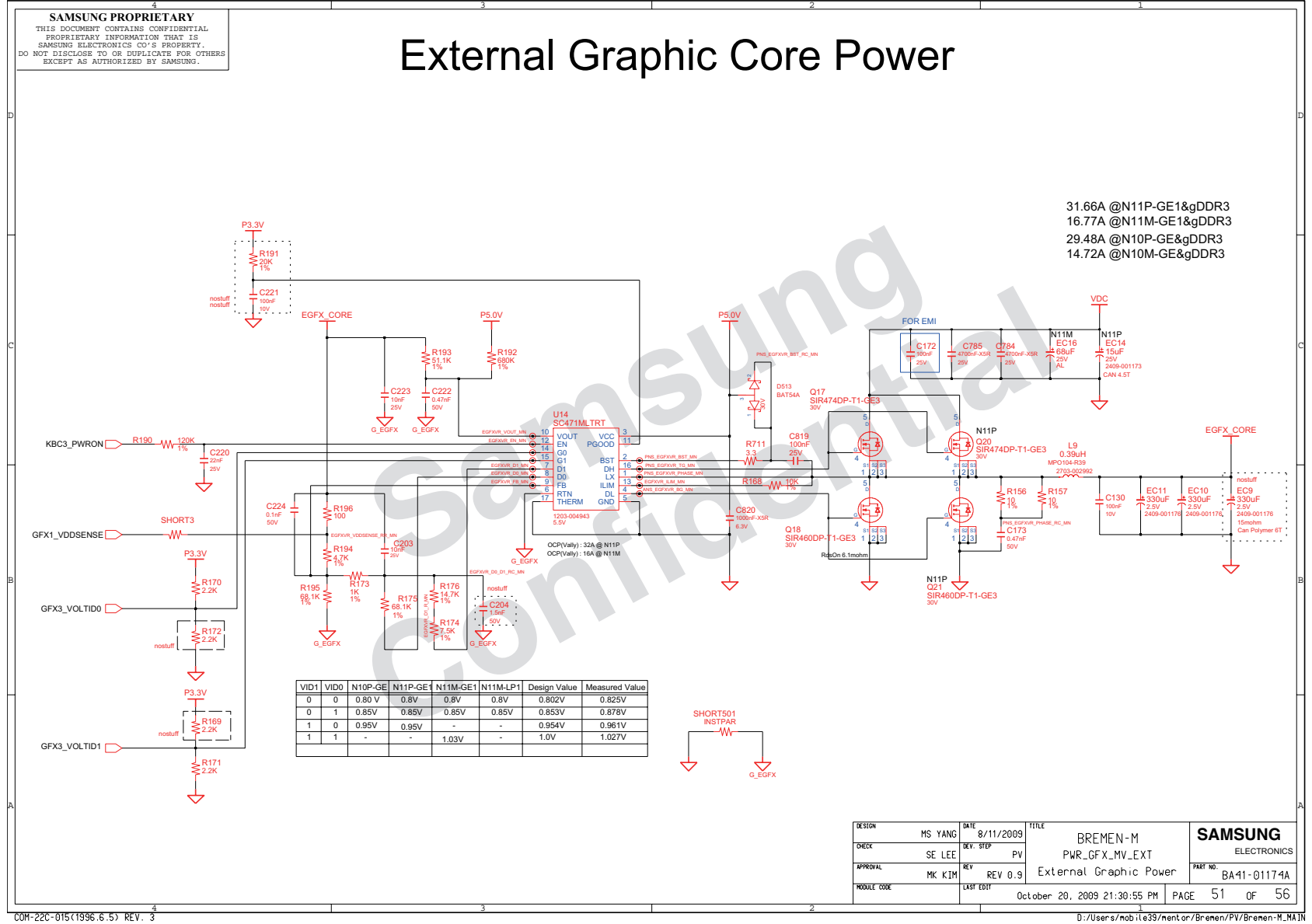
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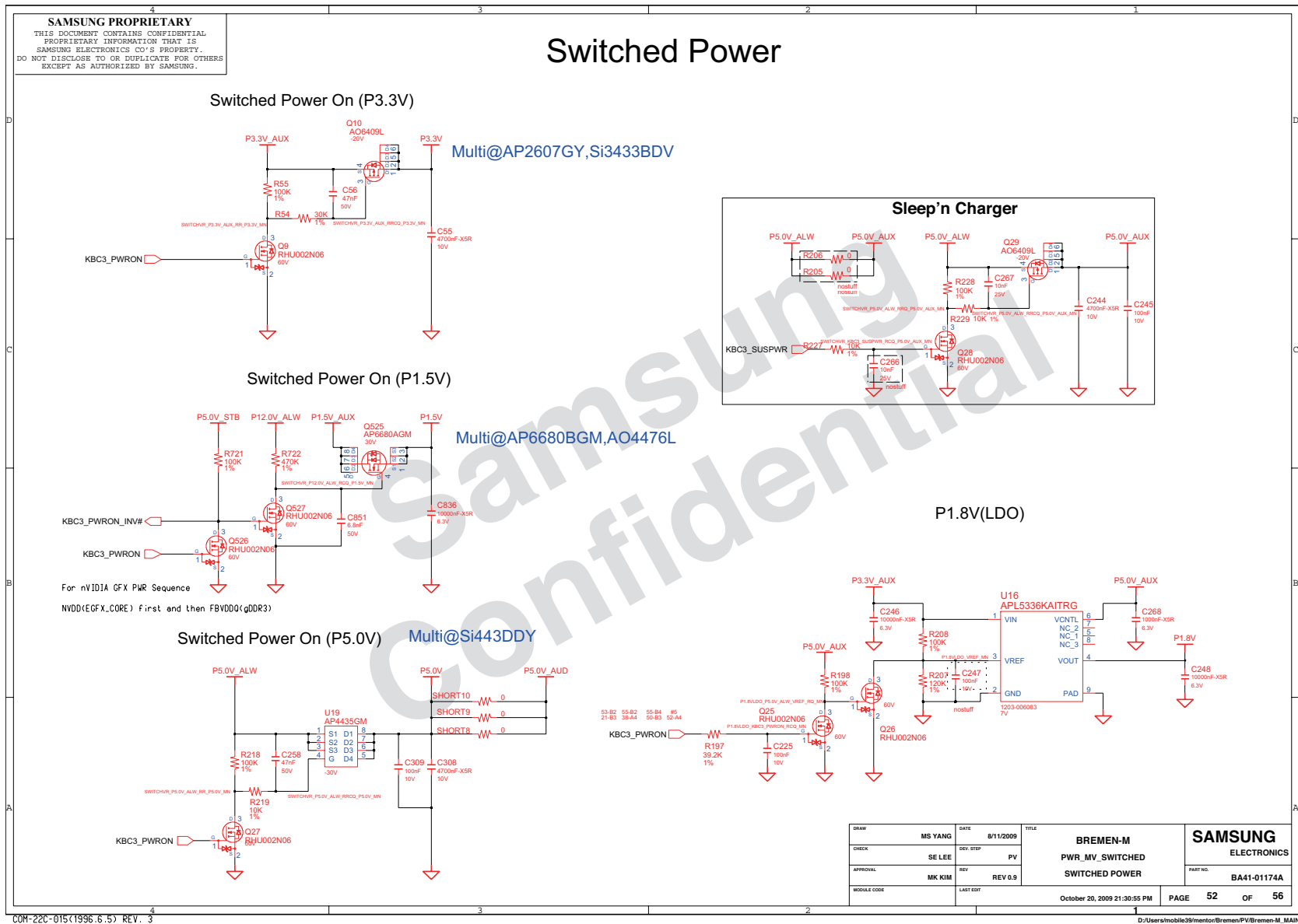
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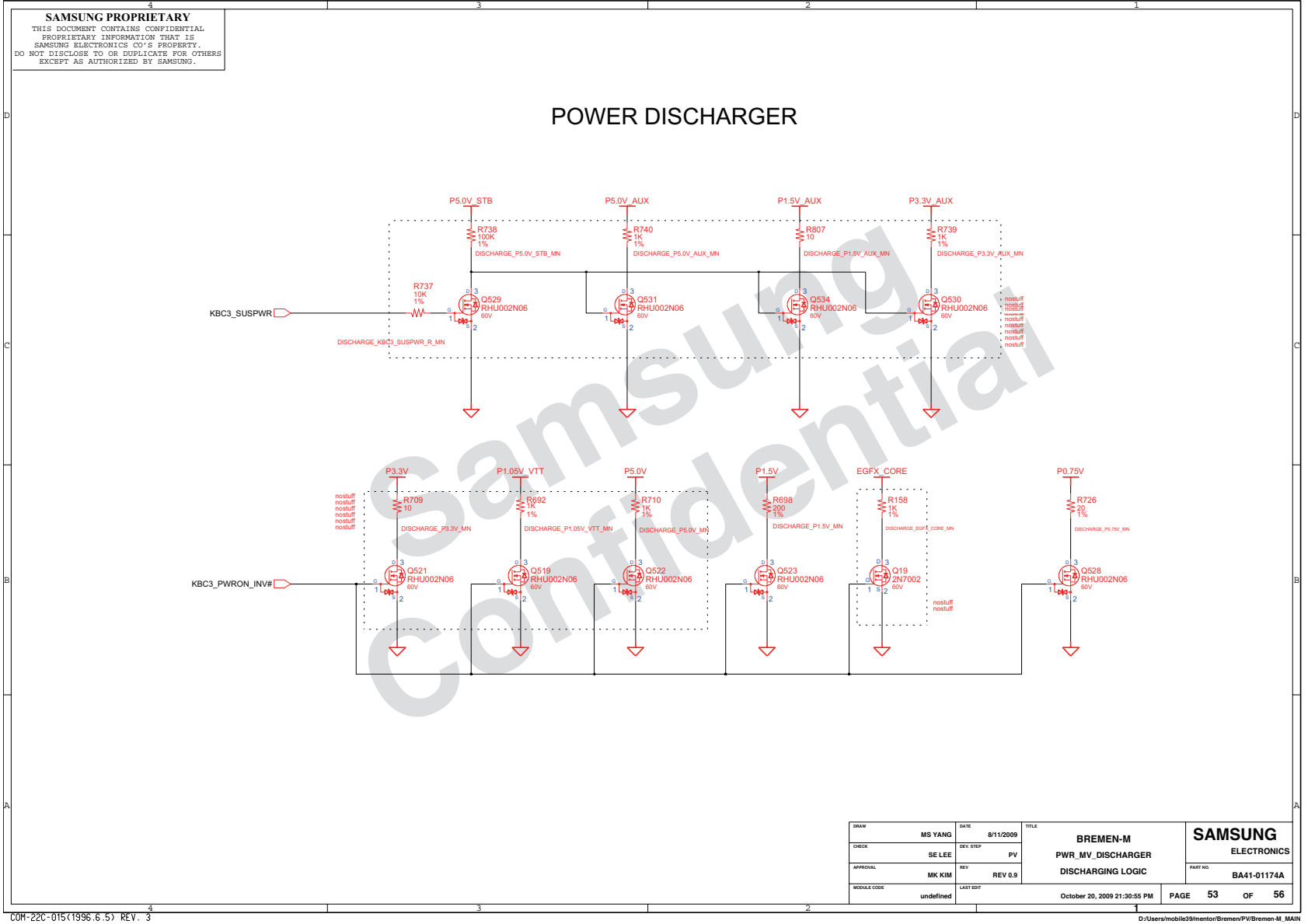
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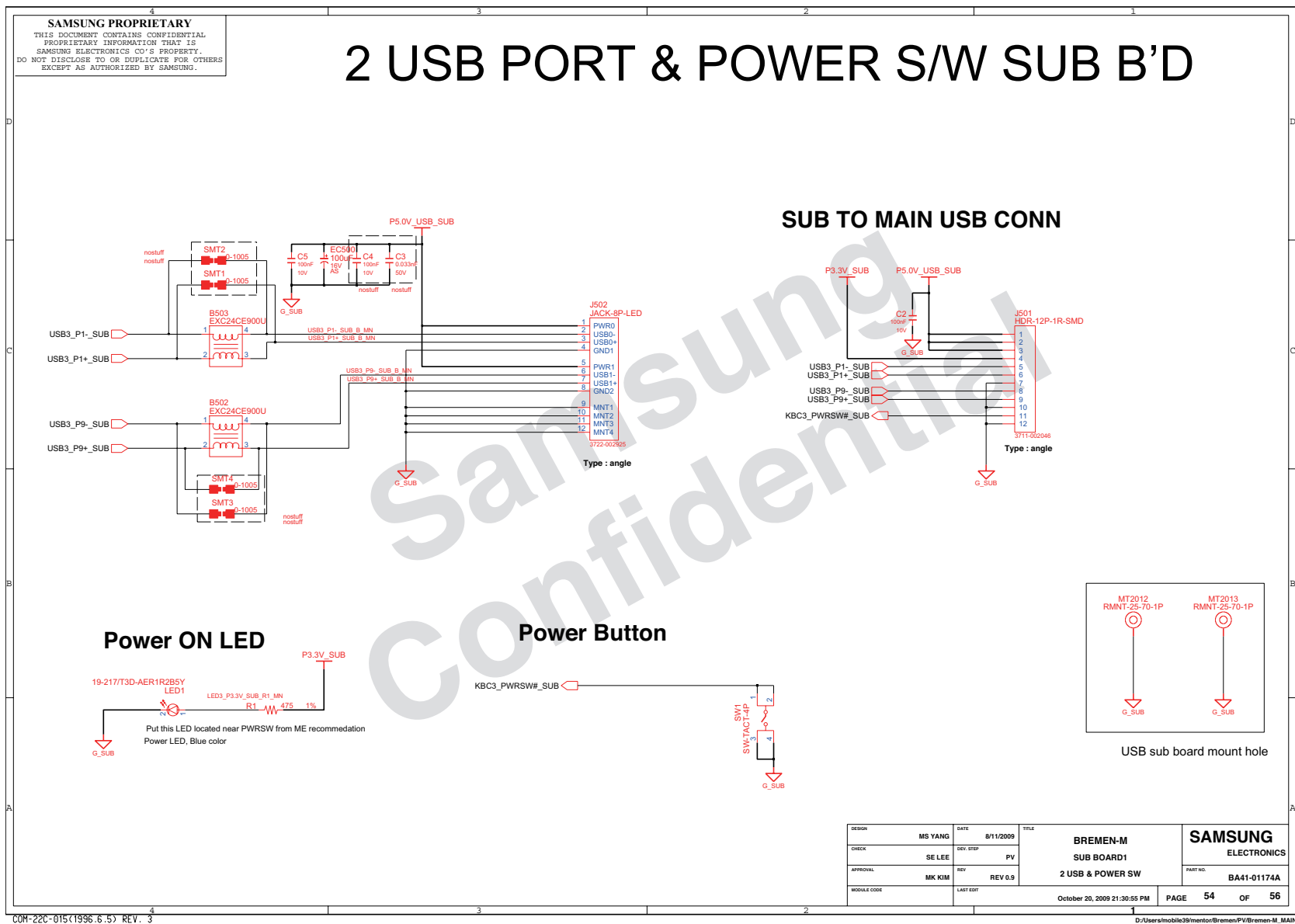
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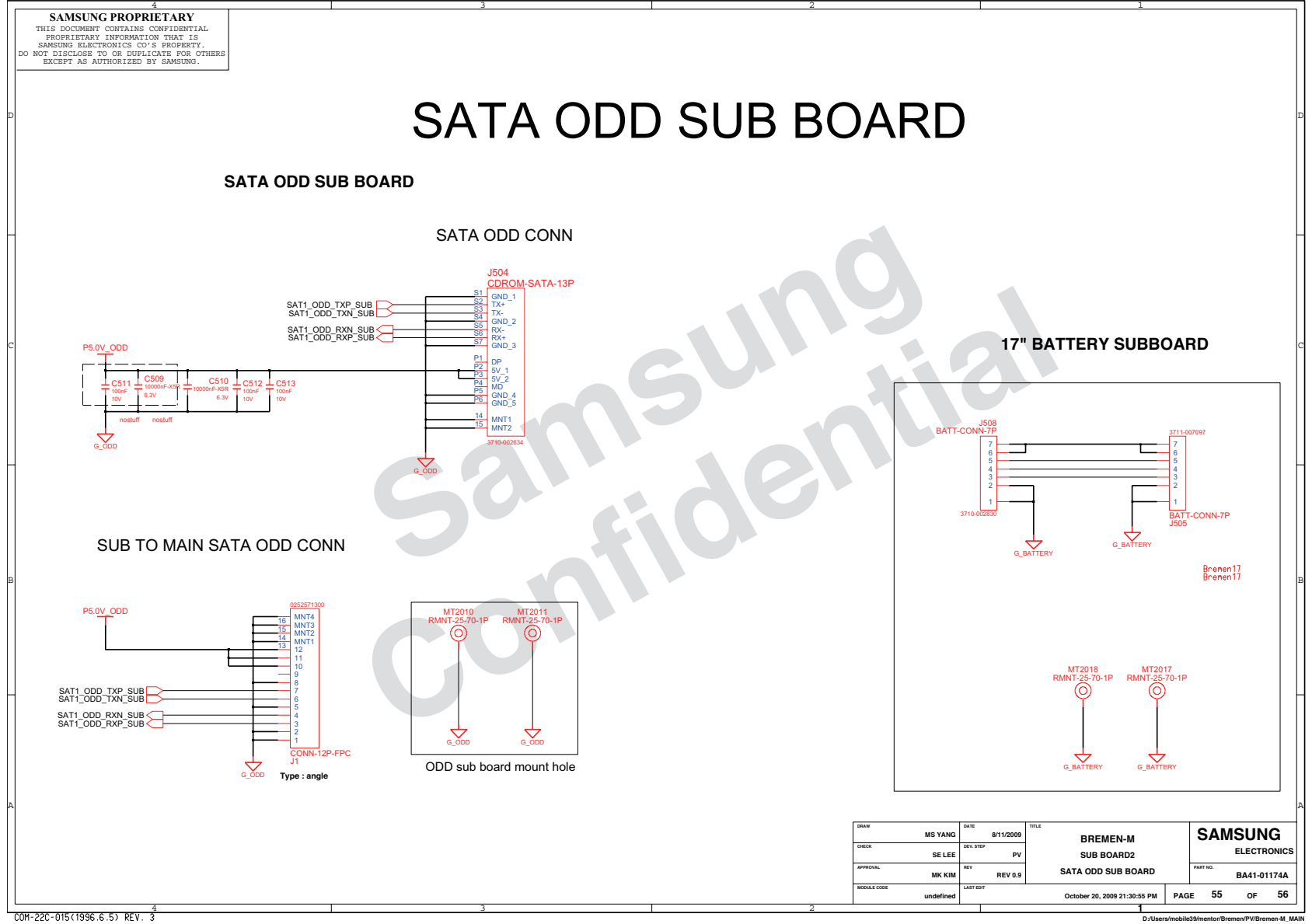
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